

AX215E

SD/MMC/eMMC Card Controller Internal Design Specification

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AX215C SD Card Controller



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CPU Features

- 8-bit 8051 CPU, with enhance extend instruction, optimized for SD, NAND Flash applications
- All instructions are single-cycled except branching instructions
- MAX 70 MIPS performance with on chip RC oscillator

Memory Features

- · 32K Byte SRAM
 - (code space and xdata space)
- 8k Byte SRAM
 - (code space 、 xdata space and 340 Byte NFC 坏列管理 复用)
- · 264 Byte RAM
 - (BCH hardware correction 复用)
- · 256 Byte DATA RAM
 - (data ram and xdata space)
- · 2K Byte VIA ROM
- - (code space)

General I/O

- · 28 GPIO pins
- · 6 SDIO pins
- All GPIO pins can be programmable as input or output individually
- All IO pins are internal pull-up selectable individually
- ALL NAND FLASH IO pins can be programmable as 4mA or 8mA or 12mA or 16mA output driving
- ALL SDIO pins can be programmable as 12mA or 16mA output driving
- · CMOS / TTL level input

SD Interface Features

- Fully supports SD card standard 1.0/1.1/2.0
- · Supports SD high capacity standard
- · Supports SPI mode
- Supports Command class 0/2/4/5/6/7/8/10
- · Speed class up to 6
- Supports host clock up to 50MHz
- Supports bus width X1/X4
- · Enhanced ESD protection

MMC/eMMC Interface Features

•

NAND Flash Interface Features

- Supports SDR/Toggle DDR1.0/ONFI2.2 interface
- · Supports X8/X16 flash
- · Supports up to 4 CE
- Supports bad column management 160 byte data mask per page
- · Supports data randomized
- Built-in 17/25/31/35/44 bit/page(1K bytes) on-the-fly ECC,优化512 Byte 的情况

Support hardware encode, decode and error correction

· Supports Two-Plane or Interleave NAND flash

Low Power Consumption

- · Operating frequency variable 10-90MHz
- Supports Sleep Mode and Idle mode
- · Fast wake up during Sleep Mode

Other Features

- · Support 1 timer
- · Support SPI, UART interface
- · Built-in RC Oscillator
- · Built-in POR and BOR
- Built-in 3.3V to 1.2V LDO
- Built-in 3.3V to 1.8V LDO

Package

· Die form

Temperature

- Operating temp.: 0°C to +70°C
- Storage temp.: -65°C to +150°C

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1 Product Overview

1.1 Description

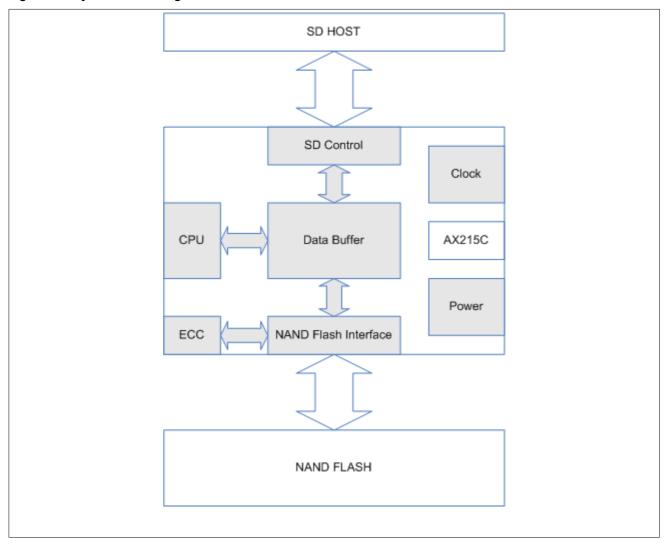
AX215E is a 8-bit 8051 microcontroller. It integrates advanced digital and analog peripherals to accommodate SD card applications.

Features:

- 8-bit 8051 CPU, with enhance extend instruction, optimized for SD, NAND flash control
- All instructions are single-cycled except branching instructions
- Fully supports SD device
- Supports high capacity standard
- Enhanced ESD protection
- Supports 528/2K/4K/8K bytes page NAND Flash
- Supports SLC/MLC/TLC NAND flash
- Supports X8/X16 flash data bus
- Supports ex3 flash data bus
- Supports Toggle DDR 1.0 flash data bus
- Supports ONFI 2.2 flash data bus
- Supports up to 4 flash chips
- Built in 17/25/29/31 bits on-the-fly ECC per sector
- Data protection during data transfer even if unplugged/power off
- On-chip POR and BOR
- On-chip Regulator
- Supports Idle mode and Sleep mode
- Supports MMC/eMMC device interface

1.2 System Architecture

Figure 1-1: System Block Diagram



2 Pin Information

2.1 Pin Assignment

2.1.1 DIE Form

Figure 2-1: Die Form PAD Location

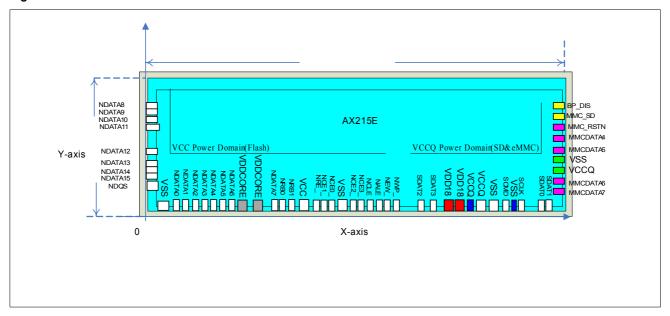


Table 2-1: Pad Coordinates

PAD Name	X-axis (um)	Y-axis (um)
NDAT8		
NDAT9		
NDAT10		
NDAT11		
NDAT12		
NDAT13		
NDAT14		
NDAT15		
NDQS		
VSS		
NDAT0		
NDAT1		
NDAT2		
NDAT3		

NDAT4		
NDAT5		
NDAT6		
VDDCORE		
VDDCORE		
NDAT7		
NRB0		
NRB1		
VCC		
NRE_		
NCE1_		
NCE0_		
VSS		
NCE2_		
NCE3_		
NCLE		
NALE		
NWE_		
NWP_		
SDDAT2		
SDDAT3		
VDD18		
VDD18		
VCCQ		
VCCQ		
VSS		
SDCMD		
VSS		
SDCLK		
SDDAT0		
SDDAT1		
MMCDATA7		
MMCDATA6		
VCCQ		
VSS		
MMCDATA5		
MMCDATA4		
MMC_RSTN		
MMC_SD		
BP_DIS		
	<u>I</u>	<u> </u>

2.2 Pin Description

Table 2-2: Pin Description

Pin	Name	Direction	Functions
1	NDAT8	I/O	Flash Data 8 P20
2	NDAT9	I/O	Flash Data 9 P21
3	NDAT10	I/O	Flash Data 10 P22
4	NDAT11	I/O	Flash Data 11 P23
5	NDAT12	I/O	Flash Data 12 P24
6	NDAT13	I/O	Flash Data 13 P25
7	NDAT14	I/O	Flash Data 14 P26
8	NDAT15	I/O	Flash Data 15 P27
9	NDQS	I/O	Flash DQS P37
10	VSS	I	Ground
11	NDATO	I/O	Flash Data 0 P10
12	NDAT1	I/O	Flash Data 1 P11
13	NDAT2	I/O	Flash Data 2 P12
14	NDAT3	I/O	Flash Data 3 P13
15	NDAT4	I/O	Flash Data 4 P14
<mark>16</mark>	NDAT5	I/O	Flash Data 5 P15
17	NDAT6	I/O	Flash Data 6 P16
18	VDDCORE	POWER OUT	1.2V core Power out
	VDDCORE	POWER OUT	1.2V core Power out
<mark>19</mark>	NDAT7	I/O	Flash Data 7 P17
20	NRB0	<mark>1/O</mark>	Flash Ready and Busy 0 P35
21	NRB1	I/O	Flash Ready and Busy 1 P36
22	VCC	POWER IN	Flash I/O power

			(FLANCE AND ADDRESS OF THE ADDRESS O
23	NRE_	I/O	Flash Read Enable P34
24	NCE1_	I/O	Flash Chip Enable 1 P01
25	NCEO_	I/O	Flash Chip Enable 0 P00
26	VSS	GND	Ground
27	NCE2_	I/O	Flash Chip Enable 2 P02
28	NCE3_	I/O	Flash Chip Enable 3 P03
29	NCLE	I/O	Flash Command Latch Enable P31
30	NALE	I/O	Flash Address Latch Enable P32
31	NWE_	I/O	Flash Write Enable P33
32	NWP_	I/O	Flash Write Protect P30
33	SDDAT2	I/O	SD Data Line 2 P44
34	SDDAT3	I/O	SD Data Line 3 P45
35	VDD18	Power out	Supply power for 1.8V Nand Flash
	VDD18	Power out	Supply power for 1.8V Nand Flash
36	VCCQ	Power in	SD/eMMC power in
	VCCQ	Power	SD/eMMC power
37	VSS	1	Ground
38	SDCMD	I/O	SD Command Line P41
39	VSS	1	Ground
40	SDCLK	I	SD Clock Line P40
41	SDDAT0	I/O	SD Data Line 0 P42
42	SDDAT1	I/O	SD Data Line 1 P43
43	MMCDATA7	I/O	SD Data Line 7 P07
44	MMCDATA6	I/O	SD Data Line 7 P06
45	VCCQ	Power	SD/eMMC power
46	VSS	I	Ground
47	MMCDATA5	I/O	SD Data Line 7 P05
48	MMCDATA4	I/O	SD Data Line 7 P04
49	MMC_RSTN	I/O	MMC H/W reset
50	MMC_SD	I	MMC/SD MODE SEL

51	BP_DIS	I	BYPASS

3 Memory Mapping and CPU Architecture

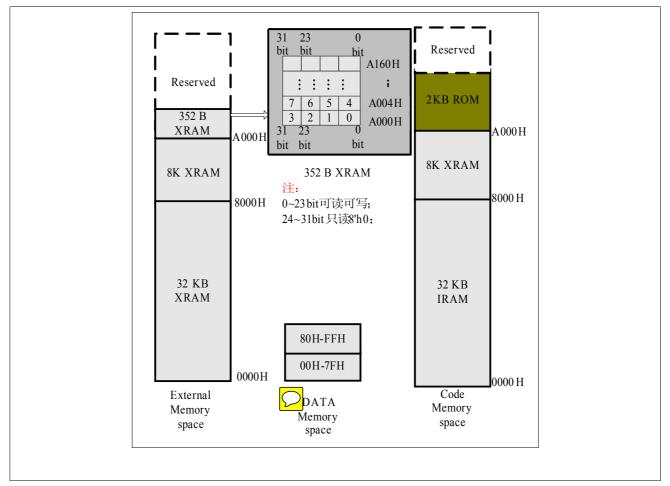
3.1 Basic Structure

AX215E CPU is modified and optimized from the standard 8051/8052 architecture. It supports most standard 8051/8052 instructions except the 4 listed below:

MOVX A, @Ri MOVX @Ri, A MOVC A, @A+PC DA

As most popular 8051/8052, AX215E supports 2 DPTRs for accessing the external memory space. However, the memory mapping is different, as shown in Figure 3-1.

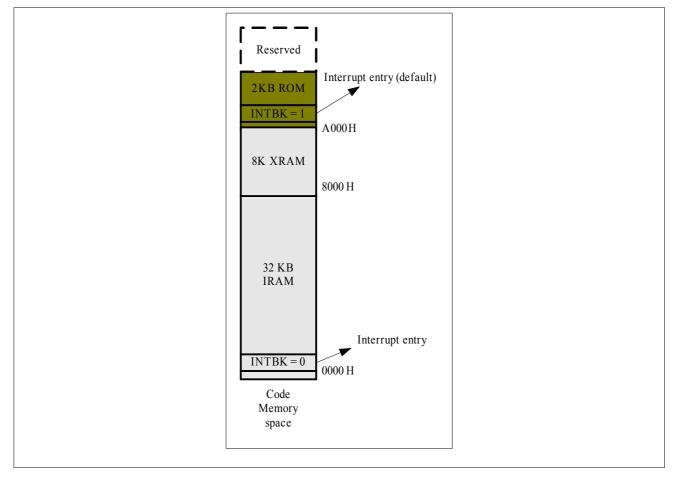
Figure 3-1: Memory Mapping



3.2 Interrupt Entry Address Mapping

After power up, the first instruction is start from A000h. That means CPU will run the boot loader program stored in MASK ROM first, and also the interrupt address is remapping start from A003h. By clearing the interrupt entry bank address control bit INTBK, the interrupt entries address will change start from 0003h as a standard 8051/8052.

Figure 3-2: Interrupt Entry Address Mapping



3.3 Data Memory – DRAM (DATA)

Data memory space (DATA) contains 256 bytes sketchpad memory, special function registers for controlling peripherals. It is also a super set of REGISTER space. To access this complex space, several addressing modes (direct, indirect, register and bit addressing) are provided. For details, please refer to the 8052 standard.

3.4 General Purpose Register (REGISTER)

General purpose registers R0 through R7 link to 32 bytes of internal data memory in the way that allows quick, efficient access. For example, the instruction MOV A, 00h using two bytes of code can be replaced by shorthand notation instruction MOV A, R0 that uses one byte of code only.

These 32 bytes of memory are put into 4 banks. Any one of them within a bank is selected by R0 through R7. Desired register bank is selected using bits RS1 and RS0 in PSW, bit 4 and bit 3 respectively (please refer to Table 3-1 for setting description). This feature eliminates the effort required to backup the registers to stack memory during context switching, in addition provides more registers for complicated algorithms.

Table 3-1: Selection of Register Bank

RS1	RS0	Bank	Mapping Addressing to DATA
0	0	0	00h-07h
0	1	1	08h-0Fh
1	0	2	10h-17h
1	1	3	18h-1Fh

3.5 Extended Data Memory – XRAM (XDATA)

To provide a unified linear memory model, AX215E organizes internal data memory that out of the scope of DATA into extended data memory space (XDATA). Total (40K + 352) bytes of XDATA (Low 32K XRAM,shared with IRAM, and high 8K XRAM, and more high 352 B XRAM) are addressed through instruction *MOVX* using two 16-bit data pointers, DPTR0 and DPTR1.

To facilitate data movement in XDATA, AX215E provides dual data pointers. Two independent data pointers are especially useful when moving, copying and manipulating large data types, such arrays, structures and unions. Based on this feature, AX215E saves many operations in manipulating pointer, comparing to single data pointer classic 8051/8052. The additional data pointer can be selected through register DPCTL. No additional instruction is introduced to distinguish these 2 pointers.

XRAM is divided the three mem , 0x0000~0x7fff as low 32K XRAM address,0x8000~0x9fff as high 8K XRAM address,0xa000~0xa160 as more high 352B XRAM address ,USB only can DMA low 32K XRAM,BCM only can DMA high 8K XRAM ,SD 、 RCMP 、 NF and Core olny can DMA low 32K and high 8K XRAM ,when more than one dma request the same XRAM at the same time ,the high priority DMA request will generate associate ack,the different DMA at the different XRAM ,which isn't priority.

Note: 352B XRAM 高的1B(24~31bits)是只读的,读的数是8'b0;低的3B(0~23bits)是可读可写的,所以可用的的XRAM只有264B

3.6 CPU Instruction Set Summary

AX215E is a high performance MCU. It executes most instructions in 1 cycle, in contrast to 12 cycles in classic 8051/8052.

3.6.1 Basic Instruction Set

Table 3-2 lists the basic instructions of AX215E, these instruction are compatible with 8051/8052 ISA.

Table 3-2: Basic Instruction Set Summary

Mnemonics Description	
-----------------------	--

ADD	A, Rn	Add register to ACC
	A, direct	Add direct byte to ACC
	A, @Ri	Add indirect byte from DRAM to ACC
	A, #data	Add immediate to ACC
ADDC	A, Rn	Add register to ACC with carry
	A, direct	Add direct byte to ACC with carry
	A, @Ri	Add indirect byte from DRAM to ACC with carry
	A, #data	Add immediate to ACC with carry
SUBB	A, Rn	Subtract register to ACC with borrow
	A, direct	Subtract direct byte to ACC with borrow
	A, @Ri	Subtract indirect byte from DRAM to ACC with borrow
	A, #data	Subtract immediate to ACC with borrow
INC	А	Increment ACC
	Rn	Increment register
	direct	Increment direct byte
	DPTR	Increment the selected DPTR
	@Ri	Increment indirect byte of DRAM
DEC	A	Decrement ACC
	Rn	Decrement register
	direct	Decrement direct byte
	DPTR	Decrement the selected DPTR
	@Ri	Decrement indirect byte of DRAM
MUL	AB	Multiply ACC and B
DIV	AB	Divide ACC by B
ANL	A, Rn	AND register to ACC
	A, direct	AND direct byte to ACC
	A, @Ri	AND indirect DRAM to ACC
	A, #data	AND immediate to ACC
	direct, A	AND ACC to direct byte
	direct, #data	AND immediate to direct byte
	C, bit	AND direct bit to carry
	C, /bit	AND complement of direct bit to carry
ORL	A, Rn	OR register to ACC
	A, direct	OR direct byte to ACC
	A, @Ri	OR indirect DRAM to ACC
	A, #data	OR immediate to ACC
	direct, A	OR ACC to direct byte
	direct, #data	OR immediate to direct byte
	C, bit	OR direct bit to carry
	C, /bit	OR complement of direct bit to carry
XRL	A, Rn	XOR register to ACC

	A, direct	XOR direct byte to ACC
	A, @Ri	XOR indirect DRAM to ACC
	A, #data	XOR immediate to ACC
	direct, A	XOR ACC to direct byte
	direct, #data	XOR immediate to direct byte
CLR	A	Clear ACC
CPL	Α	Complement ACC
RL	A	Rotate ACC left
RLC	A	Rotate ACC left through carry
RR	A	Rotate ACC right
RRC	A	Rotate ACC right through carry
SWAP	A	Swap nibbles of ACC
MOV	A, Rn	Move register to ACC
	A, direct	Move direct byte to ACC
	A, @Ri	Move indirect DRAM to ACC
	A, #data	Move immediate to ACC
	Rn, A	Move ACC to register
	Rn, direct	Move direct byte to register
	Rn, #data	Move immediate to register
	direct, A	Move ACC to direct byte
	direct, Rn	Move register to direct byte
	direct, direct	Move direct byte to direct byte
	direct, @Ri	Move indirect DRAM to direct byte
	direct, #data	Move immediate to direct byte
	@Ri, A	Move ACC to indirect DRAM
	@Ri, direct	Move direct byte to indirect DRAM
	@Ri, #data	Move immediate to indirect DRAM
	DPTR, #data	Load DPTR with 16-bit constant
	C, bit	Move direct bit to Carry
	bit, C	Move Carry to direct bit
MOVC	A, @A+DPTR	Move code byte relative DPTR to ACC
MOVX	A, @DPTR	Move external data (16-bit address) to ACC
	@DPTR, A	Move ACC to external data (16-bit address)
PUSH	direct	Push direct byte onto stack
POP	direct	Pop direct byte from stack
XCH	A, Rn	Exchange register with ACC
	A, direct	Exchange direct byte with ACC
	A, @Ri	Exchange indirect DRAM with ACC
XCHD	A, @Ri	Exchange low nibble of indirect DRAM with ACC
CLR	С	Clear carry
	bit	Clear direct bit

SETB	С	Set carry
	bit	Set direct bit
CPL	С	Complement carry
	bit	Complement direct bit
JC	rel code	Jump if carry is set
JNC	rel code	Jump if carry is not set
JB	bit, rel code	Jump if direct bit is set
JNB	bit, rel code	Jump if direct bit is not set
JBC	bit, rel code	Jump if direct bit is set and clear bit
ACALL	page code	Absolute subroutine call
LCALL	long code	Long subroutine call
RET		Return from subroutine
RETI		Return from interrupt
AJMP	page code	Absolute jump
LJMP	long code	Long jump
SJMP	rel addr	Short jump (relative address)
JMP	@A+DPTR	Jump indirect relative to DPTR
JZ	rel code	Jump if ACC equals zero
JNZ	rel code	Jump if ACC does not equal zero
CJNE	A, direct, rel code	Compare direct byte to ACC and jump if not equal
	A, #data, rel code	Compare immediate to ACC and jump if not equal
	Rn, #data, rel code	Compare immediate to Register and jump if not Equal
	@Ri, #data, rel code	Compare immediate to indirect and jump if not Equal
DJNZ	Rn, rel code	Decrement Register and jump if not zero
	direct, rel code	Decrement direct byte and jump if not zero
NOP		No operation

Notes:

Rn:

Register R0-R7 of the currently selected register bank.

@Ri:

Data RAM location addressed indirectly through R0 or R1.

rel code:

8-bit, signed (2s complement) offset relative to the first byte of the following instruction. Used by SJMP and all conditional jumps.

direct:

8-bit internal data location's address. This could be a direct-access Data RAM location (0x00-0x7F) or an SFR (0x80-0xFF).

#data:

8-bit immediate data

#data16:

16-bit immediate data

bit:

Direct-accessed bit in Data RAM or SFR

page code:

11-bit destination address used by ACALL and AJMP. The destination must be within the same 2K-byte page of program memory as the first byte of the following instruction.

long code:

16-bit destination address used by LCALL and LJMP. The destination may be anywhere within the 64K-byte program memory space.

3.6.2 Extended Instruction Set

Base on the basic instruction set, AX215E implements a set of instructions (mainly 32-bit operation) to improve the CPU performance. These instructions are named Extended Instructions (EXINST).

In the EXINST architecture, 5 sets 32-bit register are implemented, they are *ER0*, *ER1*, *ER2*, *ER3*, *ER4*. Each of them is organized by 4 SFRs:

```
ER0 = {R03, R02, R01, R00}

ER1 = {R13, R12, R11, R10}

ER2 = {R23, R22, R21, R20}

ER3 = {R33, R32, R31, R30}

ER4 = {R43, R42, R41, R40}
```

NOTE:

- 1. These 40 byte registers and R8 can be used as Direct addressing by Basic Instructions
- 2. ER4 can only be used by instruction MOV32 ER4,ERn or MOV32 ERn,ER4

Most of EXINST operations are based on these *ER*s, and some EXINST also use *ACC*, *B*, PC, or *R8* as source operands.

EXINST are described below:

Table 3-3: Extended Instructions Set Summary

	Mnemonics	Description
MOV32	ERn, EDPi	Fetch 32-bit data from XRAM and store into <i>ERn</i>
	EDPi, ERn	Store 32-bit data from <i>ERn</i> to XRAM
	ERn, ERm	Move 32-bit data from <i>ERm</i> to <i>ERn</i>
	ER4, ERn	Move 32-bit data from <i>ERn</i> to <i>ER4</i>
	ERn, ER4	Move 32-bit data from <i>ER4</i> to <i>ERn</i>
NOT32	ERn	Complement <i>ERn</i>
INC32	ERn	Increment ERn
DEC32	ERn	Decrement ERn
RAN32	EDPi, ERn	Store <i>ERn</i> to XRAM, and <i>ERn</i> updated with 32-bit pseudo random algorithm

ANL32	ERn, EDPi	AND the 32-bit data from XRAM and <i>ERn</i> , store the result into <i>ERn</i>
	EDPi, ERn	AND the 32-bit data from XRAM and ERn, store the result into XRAM
	ERn, ERm	AND <i>ERn</i> and <i>ERm</i> , store the result into <i>ERn</i>
ORL32	ERn, EDPi	OR the 32-bit data from XRAM and <i>ERn</i> , store the result into <i>ERn</i>
	EDPi, ERn	OR the 32-bit data from XRAM and <i>ERn</i> , store the result into XRAM
	ERn, ERm	OR <i>ERn</i> and <i>ERm</i> , store the result into <i>ERn</i>
XRL32	ERn, EDPi	XOR the 32-bit data from XRAM and ERn, store the result into ERn
	EDPi, ERn	XOR the 32-bit data from XRAM and <i>ERn</i> , store the result into XRAM
	ERn, ERm	XOR <i>ERn</i> and <i>ERm</i> , store the result into <i>ERn</i>
ADD32	ERp, EDPi, ERn	ADD the 32-bit data from XRAM and <i>ERn</i> , store the result into <i>ERp</i>
	EDPi, ERn, ERp	ADD <i>ERn</i> and <i>ERp</i> , store the result into XRAM
	ERp, ERn, ERm	ADD <i>ERn</i> and <i>ERm</i> , store the result into <i>ERp</i>
SUB32	ERp, EDPi, ERn	SUB <i>ERn</i> from the 32-bit data from XRAM, store the result into <i>ERp</i>
	EDPi, ERn, ERp	SUB <i>ERp</i> from <i>ERn</i> , store the result into XRAM
	ERp, ERn, ERm	SUB <i>ERm</i> from <i>ERn</i> , store the result into <i>ERp</i>
ROTR32	ERn, ER8	Rotate right ERn R8[4:0] bits, store the result into ERn
ROTL32	ERn, ER8	Rotate left ERn R8[4:0] bits, store the result into ERn
ROTR8	EACC, ER8	Rotate right ACC R8[2:0] bits, store the result into ACC
ROTL8	EACC, ER8	Rotate left ACC R8[2:0] bits, store the result into ACC
CLR32	ERn	Clear ERn
ADDDPi		ADD DPTR and {R8, B}, store the result into DPTR
SUBDPi		SUB {R8, B} from DPTR, store the result into DPTR
INCDPi		DPTR INC 1
DECDPi		DPTR DEC 1
INC4DPi		DPTR INC 4
DEC4DPi		DPTR DEC 4
MUL16	ERn	MUL <i>ERn</i> [15:0] and <i>ERn</i> [31:16], store the result into <i>ERn</i> .
DIV16	ERn	DIV <i>ERn</i> by {R8, B}, store the result into <i>Ern</i> , Store the Remainder to {R8, B}

Notes:

ERn, ERm, ERp:

32-bit register ER0-ER3. n=m=p is allowed.

ERni, ERmj:

8-bit SFR R00–R03, R10–R13, R20–R23, R30–R33. ni=mj is allowed.

EDPi:

XRAM addressing pointer DPTR0 or DPTR1.

ER8:

8-bit SFR R8.

EACC:

8-bit SFR ACC.

Indirect Addressing:

EXINST support indirect accessing XRAM by using *DPTR0* or *DPTR1*, the width unit of data in XRAM is 32-bit for the other EXINST. That means the LSB2-LSB0 or LSB1-LSB0 of DPTR are ignored during these operations. And also, *DPTR* will INC/DEC by 4 or 1 after executed if *DPAID* = 1.

When the data is fetching from XRAM to CPU or storing from CPU to XRAM, little-endian or big-endian data format is switched by *CHEND*. It's illustrated in Figure 3-3.

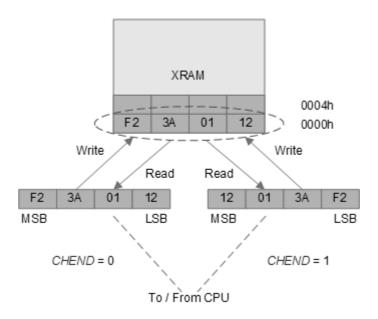


Figure 3-3: Endian Switching

Rotate Operation:

By default, the rotate instruction ROTR32 support that the data rotates right by N bits, the N is the immediate data from opcode or value of R8. However, LSHF and ASHF can change the operation as Figure 3-4 shows.

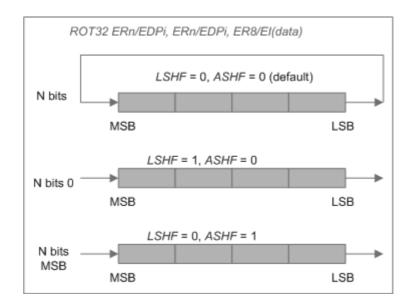


Figure 3-4: Rotate Operation

Note:

When LSHF = 1 and ASHF = 1 at the same time, LSHF is don't care.

4 Special Function Register (SFR)

4.1 SFR List

The unimplemented bits are labelled '-', never write value other than its reset value to it, otherwise unpredictable effects will be resulted. Some registers have undetermined reset value, it is labelled 'x'.

Table 4-1: SFR List

Func.	Name	Addr	Des.	Reset Value
CPU &	DPCTL	80h	DPTR Control Register	0000 0000
INT	SP	81h	Stack Pointer	0111 1111
	DP0L	82h	DPTR0 Low byte	0000 0000
	DP0H	83h	DPTR0 High byte	0000 0000
	DP1L	84h	DPTR1 Low byte	0000 0000
	DP1H	85h	DPTR1 High byte	0000 0000
	IPE	A7h	Interrupt Enable Register 1	0000 0000
	IE	A8h	Interrupt Enable Register	0000 0000
	IP	A9h	Interrupt Priority Register	0000 0000
	R8	B7h	Register 8	xxxx xxxx
	R00	C0h	Register 00	xxxx xxxx
	R01	C1h	Register 01	xxxx xxxx
	R02	C2h	Register 02	xxxx xxxx
	R03	C3h	Register 03	xxxx xxxx
	R40	C4h	Register 40	xxxx xxxx
	R41	C5h	Register 41	xxxx xxxx
	R42	C6h	Register 42	xxxx xxxx
	R43	C7h	Register 43	xxxx xxxx
	R10	C8h	Register 10	xxxx xxxx
	R11	C9h	Register 11	xxxx xxxx
	R12	CAh	Register 12	xxxx xxxx
	R13	CBh	Register 13	xxxx xxxx
	PSW	D0h	Program Status Register	0000 0000
	R20	D8h	Register 20	xxxx xxxx
	R21	D9h	Register 21	xxxx xxxx
	R22	DAh	Register 22	xxxx xxxx
	R23	DBh	Register 23	xxxx xxxx
	ACC	E0h	Accumulator	0000 0000

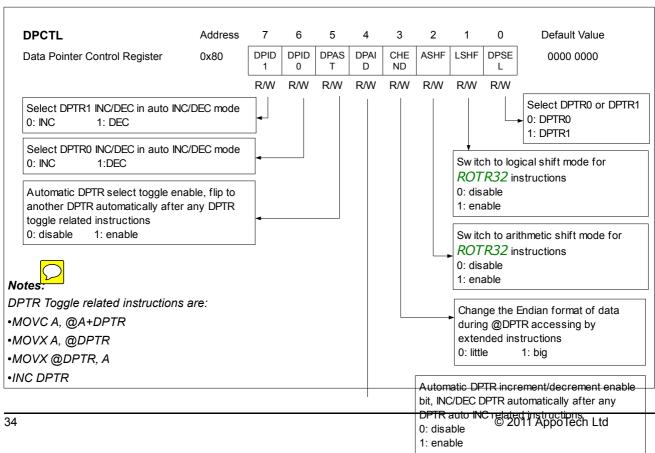
	В	F0h	Register B	0000 0000
	R30	F8h	Register 30	XXXX XXXX
	R31	F9h	Register 31	xxxx xxxx
	R32	FAh	Register 32	xxxx xxxx
	R33	FBh	Register 33	xxxx xxxx
NAND	NMCTL1	8Eh	NAND Flash Mode Control Register 1	0000 0000
Flash	NTCTL2	8Fh	NAND Flash Mode Control Register 2	0000 0000
	NXCNT0	A6h	NAND Flash DMA Start Address 0 Count	0000 0000
	NFIFO0	9Bh	NAND Flash FIFO 0	xxxx xxxx
	NFIFO1	9Ch	NAND Flash FIFO 1	xxxx xxxx
	NFIFO2	9Dh	NAND Flash FIFO 2	xxxx xxxx
	NFIFO3	9Eh	NAND Flash FIFO 3	XXXX XXXX
	NCEE	91h	NAND Flash CE Enable Register	0000 0000
	NMCTL	92h	NAND Flash Mode Control Register	0011 1000
	NTCLT0	93h	NAND Flash Timing Control 0 Register	1111 1111
	NPCTL	94h	NAND Flash Protocol Control Register	0000 0000
	NXADR0	95h	NAND Flash DMA XRAM Start Address 0 Register	xxxx xxxx
	NXADR1	96h	NAND Flash DMA XRAM Start Address 1 Register	xxxx xxxx
	NCMD1	97h	NAND Flash Command 1 Register	xxxx xxxx
	NTCTL1	98h	NAND Flash Timing Control 1 Register	0000 1111
	NPGSZ0	99h	NAND Flash Page Size 0 Register	xxxx xxxx
	NPGSZ1	9Ah	NAND Flash Page Size 1 Register	xxxx xxxx
ВСН	BXADR0	86h	BCH Codec DMA XRAM Start Address 0 Register	xxxx xxxx
Codec	BXADR1	87h	BCH Codec DMA XRAM Start Address 1 Register	xxxx xxxx
	BCTL0	88h	BCH Codec Control Register	0000 xxxx
	BCTL1	89h	BCH Codec Control Register 1	0000 0000
	BECNT	8Ah	BCH Codec ERROR Counter Register	0000 0000
	BXADR2	8Bh	BCH Codec DMA XRAM Start Address 2 Register	0000 0000
	BF0CNT	8Ch	BCH Codec DMA DATA BUFFER 0 Counter Register	0000 0000
	BPSZ	8Dh	BCH-Codec DMA DATA packet size Register	0000 0000
SD	SFLAG	90h	State Flag	000x 00x0
	SHCTL	CDh	SD Host Control	xxxx 001x
	SR1CTL	CEh		0000 0011
	SSTA	CFh	Card State Config	0000 0000
	SDODLY	D1h	Rps delay cfg	0000 0000
	SRCA0	D2h	SD RCA 0 Register	Xxxx xxxx
	SRCA1	D3h	SD RCA 1 Register	Xxxx xxxx
	SDXADR0	D4h	SD Data DMA XRAM Start Address 0 Register	Xxxx xxxx
	SDXADR1	D5h	SD Data DMA XRAM Start Address 1 Register	Xxxx xxxx
	SRXADR0	D6h	SD Response DMA XRAM Start Address 0 Register	Xxxx xxxx
	SRXADR1	D7h	SD Response DMA XRAM Start Address 1 Register	Xxxx xxxx

SDICTLDChSD data RX config register0000 0000SDOTKDDhSD Data Output Token RegisterXxxx xxxxSRDL0DEhSD Response DMA Length 0 Register0000 0011SRDL1DFhSD Response DMA Length 1 Register0000 0xx0SDDL0E1hSD Data DMA Length 0 RegisterXxxx xxxxSDDL1E2hSD Data DMA Length 1 RegisterXxxx xxxxSCCTLE3hSD Command Control Register0000 0100SRDCTLE4hSD Response Delay Control RegisterXxxx xxxxSDOCTLE5hSD data TX config register00x0 0000SINDXE6hSD Command Index Register00xx xxxxSRCTLE7hSD Response Control Register0000 0000	
SRDL0 DEh SD Response DMA Length 0 Register 0000 0011 SRDL1 DFh SD Response DMA Length 1 Register 0000 0xx0 SDDL0 E1h SD Data DMA Length 0 Register Xxxx xxxx SDDL1 E2h SD Data DMA Length 1 Register Xxxx xxxx SCCTL E3h SD Command Control Register 0000 0100 SRDCTL E4h SD Response Delay Control Register Xxxx xxxx SDOCTL E5h SD data TX config register 0000 0000 SINDX E6h SD Command Index Register 000xx xxxx	
SRDL1 DFh SD Response DMA Length 1 Register 0000 0xx0 SDDL0 E1h SD Data DMA Length 0 Register Xxxx xxxx SDDL1 E2h SD Data DMA Length 1 Register Xxxx xxxx SCCTL E3h SD Command Control Register 0000 0100 SRDCTL E4h SD Response Delay Control Register Xxxx xxxx SDOCTL E5h SD data TX config register 00x0 0000 SINDX E6h SD Command Index Register 00xx xxxx	
SDDL0 E1h SD Data DMA Length 0 Register Xxxx xxxx SDDL1 E2h SD Data DMA Length 1 Register Xxxx xxxx SCCTL E3h SD Command Control Register 0000 0100 SRDCTL E4h SD Response Delay Control Register Xxxx xxxx SDOCTL E5h SD data TX config register 00x0 0000 SINDX E6h SD Command Index Register 00xx xxxx	
SDDL1 E2h SD Data DMA Length 1 Register Xxxx xxxx SCCTL E3h SD Command Control Register 0000 0100 SRDCTL E4h SD Response Delay Control Register Xxxx xxxx SDOCTL E5h SD data TX config register 00x0 0000 SINDX E6h SD Command Index Register 00xx xxxx	
SCCTL E3h SD Command Control Register 0000 0100 SRDCTL E4h SD Response Delay Control Register Xxxx xxxx SDOCTL E5h SD data TX config register 00x0 0000 SINDX E6h SD Command Index Register 00xx xxxx	
SRDCTL E4h SD Response Delay Control Register Xxxx xxxx SDOCTL E5h SD data TX config register 00x0 0000 SINDX E6h SD Command Index Register 00xx xxxx	
SDOCTL E5h SD data TX config register 00x0 0000 SINDX E6h SD Command Index Register 00xx xxxx	
SINDX E6h SD Command Index Register 00xx xxxx	
SRCTL E7h SD Response Control Register 0000 0000	
SPEND E8h SD Pending Flag Register X000 0000	
SARG0 E9h SD Argument Register0 xxxx xxxx	
SARG1 EAh SD Argument Register1 xxxx xxxx	
SARG2 EBh SD Argument Register2 xxxx xxxx	
SARG3 ECh SD Argument Register3 xxxx xxxx	
SPICNT ADh SD Host clock counter 1000 0000	
LAST_CMD BAH SD Last CMD Register xxxx xxxx	
BOOT_CFG BDH SD boot mode configure Register 0001 0000	
Timer TCTL B0h Timer Control Register 0000 0000	
TCNT B1h Timer Counter Register xxxx xxxx	
TPR B2h Timer Period Register xxxx xxxx	
SBUF B3h Serial Port Buffer Register 0000 0000	
RAN CMPCTL AAh random compare control 0000 0000	
DOM CMPFIFO ABh random compare fifo 0000 0000	
CPERCNT ACh random compare error count 0000 0000	
CMPCTL1 AEh random compare control 1 0000)
CMPSTADR AFH compare start addr 0000 0000	
CMPDMAMT 9FH DMA 32bit data amount 0000 0000	
BCM BCMCNT B7h bad column management Counter Register xxxx xxxx	
BCMDATA A3h bad column management data xxxx xxxx	
BCMCTL A4h bad column management Control Register00	
BCMADDR A5h bad column management begin addr xxxx xxxx	
GP GPDMACNT BBH General Purpose DMA Counter Register xxxx xxxx	
UI U	
DMA GPDMAPT1 BCH General Purpose DMA port 1 xxxx xxxx	
DMA GPDMAPT1 BCH General Purpose DMA port 1 xxxx xxxx	
DMA GPDMAPT1 BCH General Purpose DMA port 1 xxxx xxxx GPDMAPT0 EDH General Purpose DMA port 0 xxxx xxxx	l

	RCCTL	B4h	RC OSC Control Register	0000 0000
	EXINTR	B5h	External Interrupt Control Register	0000 0000
	WKFLAG	B9h	Wait Flag for Wakup IDLE	0000 0000
	SCDATA	EEh	sfr data register	xxxx xxxx
	SCADDR	EFh	sfr addr register	x xxxx
	P0	F3h	Port 0 Register	xxxx xxxx
	P1	F4h	Port 1 Register	xxxx xxxx
	P2	F5h	Port 2 Register	xxxx xxxx
	P3	F6h	Port 3 Register	0001 1000
	P4	F7h	Port 4	00xx xxxx
	P0DIR	FCh	Port 0 Direction Register	0000 1111
	P1DIR	FDh	Port 1 Direction Register	1111 1111
	P2DIR	FEh	Port 2 Direction Register	1111 1111
	P3DIR	FFh	Port 3 Direction Register	0110 0000
Othe	CHIP_IDH	BFH	CHIP ID register	0000 0000
r	CHIP_IDL	BEH	CHIP ID register	0001 1110
	CHIP_DCN	A2H	CHIP DCN register	0000 0000
Notes				
: bit	accessible			

4.2 SFR Description

Register 4-1: DPCTL - Data Pointer Control Register

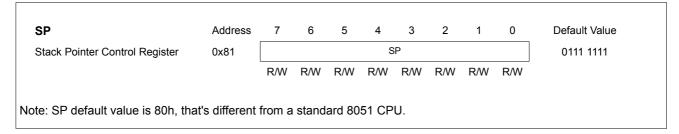


•MOV DPTR, #data16

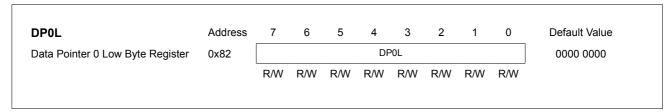
DPTR Auto INC related instructions are:

- •MOVC A, @A+DPTR
- •MOVX A, @DPTR
- •MOVX @DPTR, A

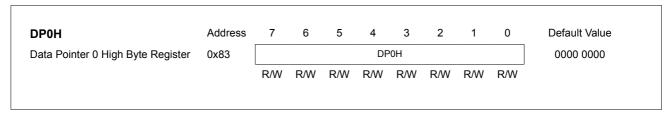
Register 4-2: SP – Stack Pointer Register



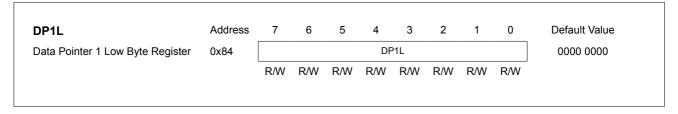
Register 4-3: DP0L – Data Pointer 0 Low Byte Register



Register 4-4: DP0H – Data Pointer 0 High Byte Register



Register 4-5: DP1L – Data Pointer 1 Low Byte Register



Register 4-6: DP1H – Data Pointer 1 High Byte Register

DP1H	Address	7	6	5	4	3	2	1	0	Default Value
Data Pointer 1 High Byte Register	0x85				DF	1H				0000 0000
		R/W								

Register 4-7: IPE – Interrupt Enable Register 1

PΕ			Address											
Inter	rupt Enable Re	egister 1	0xA7	BOR BEN_	SPIP	TMRI P	EXIP	IPE[3]	SPIE	TMRI E	EXIE	0000 0000		
				R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W			
Bit	Field	Mode	Description							Set	ting			
7	BORBEN_	R/W	BORB enabl	е						0: e	nable	1: disable		
6	SPIP	R/W	Serial Port Ir	nterrupt	Priority	Contro	ol			0: ld	ow	1: high		
5	TMRIP	R/W	Timer Interru	ıpt Prio	ity Con	trol				0: ld	ow	1: high		
4	EXIP	R/W	Port Wakeup	Port Wakeup Interrupt Priority Control								1: high		
3	IPE[3]	R/W	General pur	General purpose sfr or wake up IDLE control								1: enable		
2	SPIE	R/W	Serial Port Ir	Serial Port Interrupt Enable Bit								1: enable		
1	TMRIE	R/W	Timer Interru	Timer Interrupt Enable Bit								1: enable		
0	EXIE	R/W	Port Wakeur	Interru	lisable	1: enable								

Register 4-8: IE - Interrupt Enable Register

ΙE			Address	7	6	5	4	3	2	1	0	Default Value
Inter	rupt Enable	Register	0xA8	EA	BSIE	BIE	NFIE	SDO	SDI	SDR	SDC	0000 0000
				R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Bit	Field	Mode	Description							Set	ting	
7	EA	R/W	Global Interru	ıpt Ena	ble Bit					0: c	lisable	1: enable
6	BSIE	R/W	ECC Step 1 I	nterrup	t Enable	e Bit				0: c	lisable	1: enable
5	BIE	R/W	ECC Interrup	t Enabl	e Bit					0: c	lisable	1: enable
4	NFIE	R/W	NAND Flash	Control	Interru	pt Enat	le Bit			0: c	lisable	1: enable
3	SDO	R/W	SD Data Outp	out Inte	rrupt Er	nable B	it			0: c	lisable	1: enable
2	SDI	R/W	SD Data In In	terrupt	Enable	Bit				0: c	lisable	1: enable
1	SDR	R/W	SD Response Interrupt Enable Bit 0: disable							1: enable		
0	SDC	R/W	SD Command	d Interr	upt Ena	ble Bit				0: c	lisable	1: enable

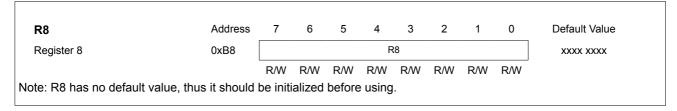
Register 4-9: IP - Interrupt Priority Register

P nterr	rupt Priority F	Register	Address 0xA9	7 HWRST_IN T_EN	6 BSIP	5 BIP	4 NFIP	3 SDO	2 SDI	1 SDR	0 SDC	Default Value 0000 0000
				-	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Bit	Field	Mode	Descript	ion						Set	ting	
7	HWRST_IN EN	T_ R/W	еММС Н	ardware res	et interr	upt ena	able				enable lisable(default)
6	BSIP	R/W	ECC Step	1 Interrupt	Priority	Contro	I			0: I	ow	1: high
5	BIP	R/W	ECC Inte	ECC Interrupt Priority Control							ow	1: high
4	NFIP	R/W	NAND FI	ash Control I	nterrup	t Priorit	y Cont	rol		0:1	ow	1: high
3	SDO	R/W	SD Data	Output Interr	upt Pric	ority Co	ntrol			0:1	ow	1: high
2	SDI	R/W	SD Data	SD Data Input Interrupt Priority Control 0: low								1: high
1	SDR	R/W	SD Resp	SD Response Interrupt Priority Control 0: low 1: high								1: high
0	SDC	R/W	SD Command Interrupt Priority Control 0: low 1: high								1: high	

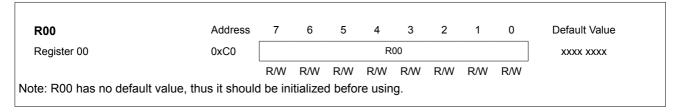
Register 4-10: WKFLAG - Wait Flag for Wakeup IDLE Register

7 WIPE3 WO - 63 WBS WO Wait BCH Syndr pending 0: low 1: high 55 WB WO Wait BCH pending 0: low 1: high 44 WNF WO Wait nand flash pending 0: low 1: high 33 WSO WO Wait SD data output pending 0: low 1: high 42 WSI WO Wait SD data input pending 0: low 1: high 41 WSR WO Wait SD response pending 0: low 1: high	3	٧K	LAG			Address	7	6	5	4	3	2	1	0	Default Value
Bit Field Mode Description Setting 7 WIPE3 WO - 6 WBS WO Wait BCH Syndr pending 0: low 1: high 5 WB WO Wait BCH pending 0: low 1: high 4 WNF WO Wait nand flash pending 0: low 1: high 3 WSO WO Wait SD data output pending 0: low 1: high 2 WSI WO Wait SD data input pending 0: low 1: high 1 WSR WO Wait SD response pending 0: low 1: high	Bit Field Mode Description Setting 7 WIPE3 WO - 6 WBS WO Wait BCH Syndr pending 0: low 1: high 5 WB WO Wait BCH pending 0: low 1: high 4 WNF WO Wait nand flash pending 0: low 1: high 3 WSO WO Wait SD data output pending 0: low 1: high 2 WSI WO Wait SD data input pending 0: low 1: high 1 WSR WO Wait SD response pending 0: low 1: high	Wait	Flag for Wal	cup IDLE Reg	ister	0xB9		WBS	WB	WNF	wso	WSI	WSR	WEX	0000 0000
7 WIPE3 WO - 6 WBS WO Wait BCH Syndr pending 0: low 1: high 5 WB WO Wait BCH pending 0: low 1: high 4 WNF WO Wait nand flash pending 0: low 1: high 3 WSO WO Wait SD data output pending 0: low 1: high 2 WSI WO Wait SD data input pending 0: low 1: high 1 WSR WO Wait SD response pending 0: low 1: high	7 WIPE3 WO - 6 WBS WO Wait BCH Syndr pending 0: low 1: high 5 WB WO Wait BCH pending 0: low 1: high 4 WNF WO Wait nand flash pending 0: low 1: high 3 WSO WO Wait SD data output pending 0: low 1: high 2 WSI WO Wait SD data input pending 0: low 1: high 1 WSR WO Wait SD response pending 0: low 1: high						W0	W0	W0	W0	W0	W0	W0	W0	
WBS WO Wait BCH Syndr pending 0: low 1: high WB WO Wait BCH pending 0: low 1: high WNF WO Wait nand flash pending 0: low 1: high WSO WO Wait SD data output pending 0: low 1: high WSI WO Wait SD data input pending 0: low 1: high WSR WO Wait SD response pending 0: low 1: high	6 WBS WO Wait BCH Syndr pending 0: low 1: high 5 WB WO Wait BCH pending 0: low 1: high 4 WNF WO Wait nand flash pending 0: low 1: high 3 WSO WO Wait SD data output pending 0: low 1: high 2 WSI WO Wait SD data input pending 0: low 1: high 1 WSR WO Wait SD response pending 0: low 1: high	Bit	Field	Mode	De	scription							Set	ting	
WB WO Wait BCH pending 0: low 1: high WNF WO Wait nand flash pending 0: low 1: high WSO WO Wait SD data output pending 0: low 1: high WSI WO Wait SD data input pending 0: low 1: high WSR WO Wait SD response pending 0: low 1: high	WB WO Wait BCH pending 0: low 1: high WNF WO Wait nand flash pending 0: low 1: high WSO WO Wait SD data output pending 0: low 1: high WSI WO Wait SD data input pending 0: low 1: high WSR WO Wait SD response pending 0: low 1: high	7	WIPE3	WO									-		
WNF WO Wait nand flash pending 0: low 1: high WSO WO Wait SD data output pending 0: low 1: high WSR WO Wait SD response pending 0: low 1: high USR WO Wait SD response pending 0: low 1: high	WNF WO Wait nand flash pending 0: low 1: high WSO WO Wait SD data output pending 0: low 1: high USD WSI WO Wait SD data input pending 0: low 1: high WSR WO Wait SD response pending 0: low 1: high USR WSI WO Wait SD response pending 0: low 1: high	6	WBS	WO	W	ait BCH Syr	ndr pen	ding					0: I	ow	1: high
3 WSO WO Wait SD data output pending 0: low 1: high 2 WSI WO Wait SD data input pending 0: low 1: high 1 WSR WO Wait SD response pending 0: low 1: high	3 WSO WO Wait SD data output pending 0: low 1: high 2 WSI WO Wait SD data input pending 0: low 1: high 1 WSR WO Wait SD response pending 0: low 1: high	5	WB	WO	W	ait BCH per	iding						0:1	ow	1: high
2 WSI WO Wait SD data input pending 0: low 1: high 1 WSR WO Wait SD response pending 0: low 1: high	2 WSI WO Wait SD data input pending 0: low 1: high 1 WSR WO Wait SD response pending 0: low 1: high	4	WNF	WO	W	ait nand flas	sh pend	ing					0:1	ow	1: high
1 WSR WO Wait SD response pending 0: low 1: high	1 WSR WO Wait SD response pending 0: low 1: high	3	WSO	WO	W	ait SD data	output ¡	pending					0:1	ow	1: high
		2	WSI	WO	W	ait SD data	input pe	ending					0: I	ow	1: high
0 WEX WO Wait external INT pending 0: low 1: high	0 WEX WO Wait external INT pending 0: low 1: high	1	WSR	WO	W	ait SD respo	onse pe	nding					0:1	ow	1: high
		0	WEX	WO	W	ait external	INT per	nding					0:1	ow	1: high

Register 4-11: R8 - Register 8



Register 4-12: R00 - Register 00



Register 4-13: R01 - Register 01

R01	Address	7	6	5	4	3	2	1	0	Default Value		
Register 01												
		R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W			
Note: R01 has no default	value, thus it should	d be in	itialize	d befor	re usin	g.						

Register 4-14: R02 - Register 02

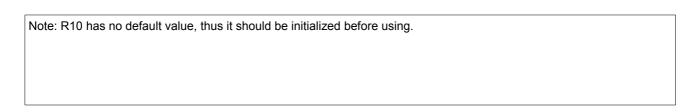
R02	Address	7	6	5	4	3	2	1	0	Default Value
Register 02	0xC2				R	02				xxxx xxxx
		R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Note: R02 has no default value, th	us it should	d be ini	tialize	d befor	e usin	g.				

Register 4-15: R03 - Register 03

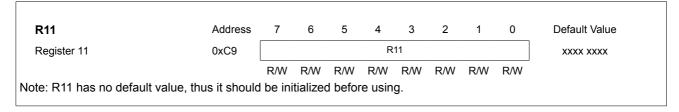
R03	Address	7	6	5	4	3	2	1	0	Default Value
Register 03	0xC3				R	03				xxxx xxxx
		R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Note: R03 has no default v	alue, thus it should	d be in	itialize	d befoi	re usin	g.				

Register 4-16: R10 - Register 10

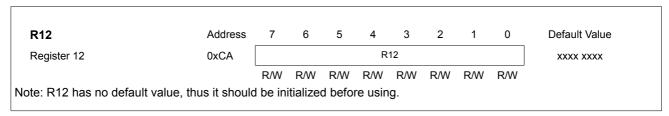
R10	Address	7	6	5	4	3	2	1	0	Default Value
Register 10	0xC8				R	10				XXXX XXXX
		R/W								



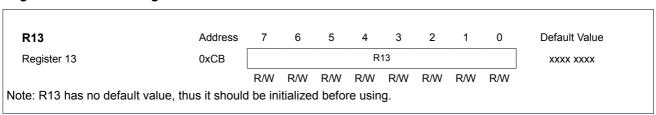
Register 4-17: R11 - Register 11



Register 4-18: R12 - Register 12



Register 4-19: R13 – Register 13



Register 4-20: PSW - Program Status Register

PSW			Address	7	6	5	4	3	2	1	0	Default Value
Progra	am Status Re	gister	0xD0	CY	AC	EC	RS1	RS0	OV	EZ	Р	0000 0000
				R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Bit	Field	Mode	Descript	ion								Setting
7	CY	R/W	Carry flag	g from l	oit 7							-
6	AC	R/W	Auxiliary	carry fl	ag							-
5	EC	R/W	Extended	carry	flag, onl	y affect	by ext	tend in	structio	on		-
4	RS1	R/W	Register 00: bank 01: bank)	elector							-
3	RS0	R/W	10: bank 11: bank	2								-
2	OV	R/W	Overflow	flag								-
1	EZ	R/W	Extended	zero f	ag, only	/ affect	by exte	end ins	structio	ns		-
0	Р	R/W	Parity fla	g g								-

Register 4-21: R20 - Register 20

R20	Address	7	6	5	4	3	2	1	0	Default Value
Register 20	0xD8				R	20				xxxx xxxx
		R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Note: R20 has no default va	lue, thus it should	d be in	itialize	d befoi	re usin	g.				

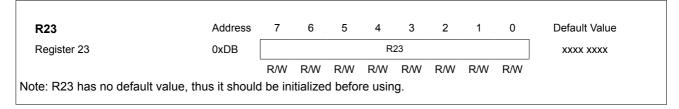
Register 4-22: R21 – Register 21

R21	Address	7	6	5	4	3	2	1	0	Default Value
Register 21	0xD9				R	21				xxxx xxxx
		R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Note: R21 has no default v	alue, thus it should	d be in	itialize	d befor	e usin	g.				

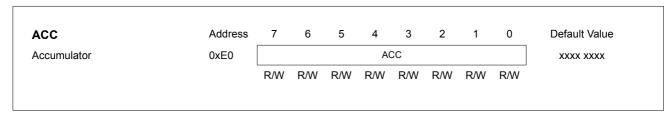
Register 4-23: R22 – Register 22

R22	Address	7	6	5	4	3	2	1	0	Default Value
Register 22	0xDA				R	22				xxxx xxxx
		R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Note: R22 has no default value, the	us it should	d be ini	tialize	d befor	re usin	g.				

Register 4-24: R23 - Register 23



Register 4-25: ACC – Accumulator



Register 4-26: B - B Register

В	Address	7	6	5	4	3	2	1	0	Default Value
B Register	0xF0				E	3				xxxx xxxx
		R/W								

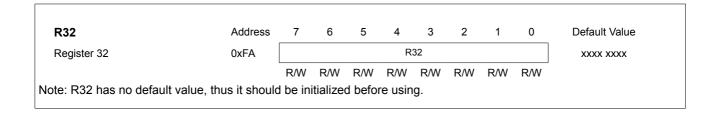
Register 4-27: R30 - Register 30

R30	Address	7	6	5	4	3	2	1	0	Default Value
Register 30	0xF8				R	30				xxxx xxxx
		R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Note: R30 has no default value, th	us it should	d be ini	tialize	d befor	e usin	g.				

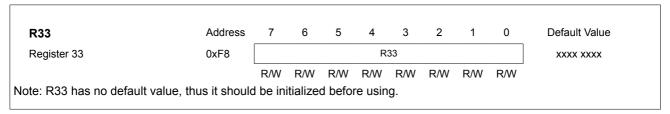
Register 4-28: R31 - Register 31

R31	Address	7	6	5	4	3	2	1	0	Default Value
Register 31	0xF9				R	31				xxxx xxxx
		R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Note: R31 has no default value	, thus it should	d be in	itialize	d befor	re usin	g.				

Register 4-29: R32 - Register 32



Register 4-30: R33 - Register 33



Register 4-31: R40 - Register 40

R40	Address	7	6	5	4	3	2	1	0	Default Value
Register 40	0xC4				R	40				xxxx xxxx
		R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	•
Note: R40 has no default value	e, thus it should	d be in	itialize	d befoi	re usin	g.				

Register 4-32: R41 - Register 41

R41	Address	7	6	5	4	3	2	1	0	Default Value
Register 41	0xC5				R	41				xxxx xxxx
		R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Note: R41 has no default val	ue, thus it should	d be in	itialize	d befoi	re usin	g.				

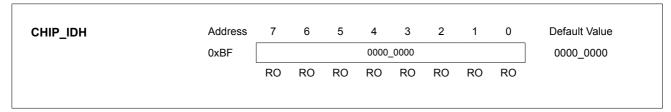
Register 4-33: R42 – Register 42

R42	Address	7	6	5	4	3	2	1	0	Default Value
Register 42	0xC6		R42					XXXX XXXX		
		R/W	R/W							
Note: R42 has no default value, thus it should be initialized before using.										

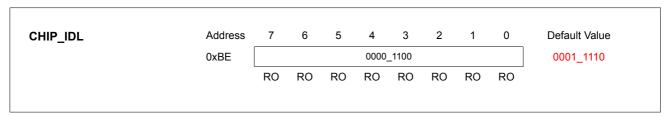
Register 4-34: R43 - Register 43

R43 Address 6 3 1 0 Default Value Register 43 0xC7 R43 xxxx xxxx R/W R/W R/W R/W R/W R/W R/W R/W Note: R43 has no default value, thus it should be initialized before using.

Register 4-35: CHIP_IDH - Register 42



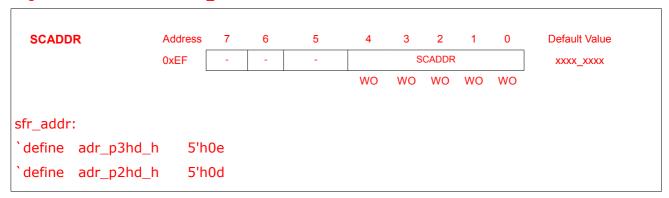
Register 4-36: CHIP_IDL - Register 42



Register 4-37: CHIP_DCN - Register 42

CHIP_DCN	Address 0xC0	7	6	5		3	2	1	0	Default Value
	CXCC	RO	RO	RO	RO	_	RO	RO	RO	5555_5555

Register 4-38: SCADDR -ADDR_SFR



adr_p1hd_h	5'h0c
adr_p0hd_h	5'h0b
adr_p4hd	5'h0a
adr_aipcon	5'h09
adr_p4plp	5'h08
adr_p3plp	5'h07
adr_p2plp	5'h06
adr_p1plp	5'h05
adr_p0plp	5'h04
adr_p3hd	5'h03
	EILOO
adr_p2hd	5'h02
adr_p2hd adr_p1hd	5 h02
	adr_p0hd_h adr_p4hd adr_aipcon adr_p4plp adr_p3plp adr_p2plp adr_p1plp adr_p0plp adr_p3hd

Register 4-39: SCDATA

 SCDATA
 Address
 7
 6
 5
 4
 3
 2
 1
 0
 Default Value

 0xEE
 SCDATA
 xxxxx_xxxx

 WO
 WO
 WO
 WO
 WO
 WO
 WO
 WO

操作方法:

比如你想打开**P3**口的上拉,具体操作如下:

MOV SCADDR,#addr_p3plp

MOV SCDATA, #DATA

如果你想读P3口的上拉值到A,具体操作如下:

MOV SCADDR,# addr_p3plp

MOV A,SCDATA

note:

_关于驱动电流配置的描述:

p00~p03这四个IO的驱动电流,对应的配置位为:

p03	p02	p01	p00
SCDATA[7:6]	SCDATA[5:4]	SCDATA[3:2]	SCDATA[1:0]

MOV SCADDR,#addr_p0hd

MOV SCDATA, #DATA

p10~p13这四个IO的驱动电流,对应的配置位为:

p13	p12	p11	p10	
SCDATA[7:6]	SCDATA[5:4]	SCDATA[3:2]	SCDATA[1:0]	

MOV SCADDR,#addr_p1hd

MOV SCDATA, #DATA

p14~p17这四个IO的驱动电流,对应的配置位为:

p17	p16	p15	p14	
SCDATA[7:6]	SCDATA[5:4]	SCDATA[3:2]	SCDATA[1:0]	

MOV SCADDR,#addr_p1hd_h

MOV SCDATA, #DATA

p20~p23这四个IO的驱动电流,对应的配置位为:

p23	p22	p21	p20	
SCDATA[7:6]	SCDATA[5:4]	SCDATA[3:2]	SCDATA[1:0]	

MOV SCADDR, #addr_p2hd

MOV SCDATA, #DATA

p24~p27这四个IO的驱动电流,对应的配置位为:

p27	p26	p25	p24	
SCDATA[7:6]	SCDATA[5:4]	SCDATA[3:2]	SCDATA[1:0]	

MOV SCADDR,#addr_p2hd_h

MOV SCDATA, #DATA

p30~p33这四个IO的驱动电流,对应的配置位为:

p33	p32	p31	p30	
SCDATA[7:6]	SCDATA[5:4]	SCDATA[3:2]	SCDATA[1:0]	

MOV SCADDR, #addr_p3hd

MOV SCDATA, #DATA

p34~p37这四个IO的驱动电流,对应的配置位为:

p37	p36	p35	p34	
SCDATA[7:6]	SCDATA[5:4]	SCDATA[3:2]	SCDATA[1:0]	

MOV SCADDR,#addr_p3hd_h

MOV SCDATA, #DATA

对应的驱动电流为:

' 00	4mA
′ 01	8mA
' 10	12mA
′ 11	16mA

p04~p07这四个IO的驱动电流,对应的配置位为:(注意:p04~p07这4个IO的驱动只有两种选择)

p07	p00	6 p05	p04	
SCDATA[3	SCDA	TA[2] SCDAT	A[1] SCDATA[0]	

MOV SCADDR,#addr_p0hd_h MOV SCDATA,#DATA

对应的驱动电流为:

′ 0	12mA
′1	16mA

5 GPDMA

GPDMAPT0

	01 B 1 M H 1 V								
Position	7	6	5	4	3	2	1	0	
Name	GPDM	APT0L			GPDMAPT0H/ GPDMAPT0L				
Default	X	X	X	X	X	X	X	X	
Access	W	W	W	W	W	W	W	W	

GPDMAPT0: GPDMA pointer 0

这个寄存器在GPDMA模式时用于指定从memory的哪里开始读数据,即源地址。这个memory的mapping与CPU xdata一样。因为搬运数据时是以32bit为单位,所以这个寄存器有14位。

硬件纠错手动模式时,这个寄存器需要写入错误位置的起始地址,即(0XA000 + BXADR2)

操作这个寄存器需要写两次,第一次写高6bit,第二次写低8bit的地址;

GPDMAPT1

Position	7	6	5	4	3	2	1	0
Name	GPDM	APT1L			GPDMAPT1H/ GPDMAPT1L			
Default	X	X	X	X	X	X	X	X
Access	W	W	W	W	W	W	W	W

GPDMAPT1: GPDMA pointer 1

这个寄存器在GPDMA模式时用于指定从memory的哪里开始写数据,即目标地址。这个memory的mapping与CPU xdata一样。因为搬运数据时是以32bit为单位,所以这个寄存器有14位。

操作这个寄存器需要写两次,第一次写高6bit,第二次写低8bit的地址;

GPDMACON

Position	7	6	5	4	3	2	1	0
Name				WKGSEL	EC_DONE	AUTO_EC	MOD	ESEL
Default	0	0	0	0	1	0	0	0
Access	_		_	_	R/W	R/W	R/W	R/W

WKGSEL: wake up group select

0: group0 (DP/DM)

1: group1 (NDAT12/NCE7)

EC DONE: Error correct done

0: Not done

1: Done

手动模式时,写1不做任何动作,写0时会kick start error correct。自动模式时,写这bit没作用。

AUTO EC: Auto Error correct

0: manual error correct
1: auto error correct

MODESEL: Mode Select

00: IDLE mode.

01: General Purpose DMA. 当完成所有DMA时,会自动变为IDLE MODE.

10: Error correct mode

GPDMACNT

Position	7	6	5	4	3	2	1	0
Name	GPDMACNTL			GPDMACNTH/ GPDMACNTL				
Default	X	X	X	X	X	X	X	X
Access	W	W	W	W	W	W	W	W

GPDMACNT: DMA的数量。以32bit为单位,需要减1,例如写入0表示DMA1个32bit数据。 当完成所有DMA时,MODESEL会自动变为IDLE MODE。共13bit,最多可以一次过搬运8192 个32bit数据。

硬件纠错手动模式时,这个寄存器需要写入错误bit数,即BECNT。

Operation Guide

GPDMA 🔽



1.指定源地址:例如逻辑地址0x8000为源地址,因为是以32bit为单位,所以需要右移2 位:

GPDMAPT0 = ((0X8000>>2)>>8);GPDMAPT0 = ((0X8000 >> 2) & 0X00FF);

2.指定目标地址:例如逻辑地址0x4000为目标地址,因为是以32bit为单位,所以需要右 移2位:

GPDMAPT1 = ((0X4000>>2)>>8);GPDMAPT1 = ((0X4000>>2) & 0X00FF);

3.指定数量,例如16个32位数,需要减1:

GPDMACNT = 0x00:

GPDMACNT = 0x0F;

4. Enable GPDMA mode:

GPDMACON = 0X01;

5.等待MODESEL变为IDLE MODE。

Error Correct Auto Mode

- 1.必须在BCH进入decode mode之前Enable EC mode, 清零ec done, 选择自动模式: GPDMACON = 0X06;
- 2.正常进行BCH decode流程, bch done有效之后,必须再等待ec done有效之后再将 bch done清0(bch done被清零的时候同时也会清零ec done):

while((GPDMACON & 0X08) != 0X08);

```
BCTL0 &= ~0X80;
```

- 3.继续进行decode 流程,每次等待bch done的时候都按第二步进行即可。
- 4.完成所有数据的decode之后,需要退出ec_mode GPDMACON = 0X00;

Error Correct Manual Mode

- 1.必须在BCH进入decode mode之前Enable EC mode, 选择手动模式: GPDMACON = 0X0A;
- 2.正常进行BCH decode流程,第一次bch_done有效之后,存在错误且不大于可纠错范围,则写上错误位置起始地址和错误数量,并kick start error correct

```
if((BCTL0 & 0X60) == 0X20)
{
         GPDMAPT0 = 0XA0 >> 2;
         GPDMAPT0 = BXADR2 >> 2;
         GPDMACNT = 0X00;
         GPDMACNT = BECNT;
         GPDMACON &= ~0X08;//kick start
}
BCTL0 &= ~0X80;
```

3.如果只有一包数据,等待ec_done即可完成decode流程。连续decode请跳过这步,直接看step4

```
while((GPDMACON & 0X08) != 0X08);
GPDMACON = 0X00;
```

4.继续进行decode 流程,下一个bch_done有效的时候,如果存在错误(不管是否大于可纠错范围),则必须确认上一包数据已经硬件纠错完成才能clear bch_done和kick start第二次纠错。

```
if((BCTL0 & 0X20) == 0X20)//have error
{
    while((GPDMACON & 0X08) != 0X08);//wait before error correct done
    if((BCTL0 & 0X40) != 0X40)//not too many error
    {
        GPDMAPT0 = 0XA0 >> 2;
        GPDMAPT0 = BXADR2 >> 2;
        GPDMACNT = 0X00;
        GPDMACNT = BECNT;
        GPDMACON &= ~0X08;//kick start
    }
}
BCTL0 &= ~0X80;
```

5.循环进行step3,完成所有数据decode后,跳到step3,等硬件完成最后一包数据的纠错即可结束。

6 Interrupt Processing

AX215E extends the interrupt system to support totally 11 interrupt sources with two priority levels. Each interrupt source has one or more associated interrupt-pending flag(s) located in an SFR. When a peripheral or external source meets a valid interrupt condition, the associated interrupt-pending flag is set to logic 1.

If interrupts are enabled for the source, an interrupt request is generated when the interrupt-pending flag is set. As soon as execution of the current instruction is complete, the CPU backs up the location of the next instruction to STACK and then begins execution of an interrupt service routine (ISR). Each ISR must end with an RETI instruction, which returns program execution to the next instruction that would have been executed if the interrupt request had not occurred. If interrupts are not enabled, the interrupt-pending flag is ignored by the hardware and program execution continues as normal. (The interrupt-pending flag is set to logic 1 regardless of the interrupt's enable/disable state.)

Each interrupt source can be individually enabled or disabled through the use of an associated interrupt enable bit in the Interrupt Enable SFRs. However, interrupts must first be globally enabled by setting the EA bit (IE.7) to logic 1 before the individual interrupt enables are recognized.

Setting the EA bit to logic 0 disables all interrupt sources regardless of the individual interrupt-enable settings. Note that interrupts which occur when the EA bit is set to logic 0 will be held in a pending state, and will not be serviced until the EA bit is set back to logic 1.

Some interrupt-pending flags are automatically cleared by the hardware when the CPU vectors to the ISR. However, most are not cleared by the hardware and must be cleared by software before returning from the ISR. If an interrupt-pending flag remains set after the CPU completes the return-from-interrupt (RETI) instruction, a new interrupt request will be generated immediately and the CPU will re-enter the ISR after the completion of the next instruction.

6.1 Interrupt Sources and Vectors

The CPU supports 11 interrupt sources. Software can simulate an interrupt by setting some interrupt-pending flags to '1'. If interrupts are enabled for the flag, an interrupt request will be generated and the CPU will vector to the ISR address associated with the interrupt-pending flag. MCU interrupt sources, associated vector addresses, priority order, and control bits are summarized in Table 6-1. Refer to the data sheet section associated with a particular on-chip peripheral for information regarding valid interrupt conditions for the peripheral and the behaviour of its interrupt-pending flag(s).

6.2 Interrupt Priorities

Each interrupt source can be individually programmed to one of two priority levels: low or high. A low priority interrupt service routine can be pre-empted by a high priority interrupt. A high priority interrupt cannot be pre-empted. Each interrupt has an associated interrupt priority bit in an SFR (IP, IPE) used to configure its priority level. Low priority is the default. If two interrupts are recognized simultaneously, the interrupt with the higher priority is serviced first. If both interrupts have the same priority level, a fixed priority order is used to arbitrate, given in Table 6-1.

Table 6-1: Summary of Interrupts

INT Source	Vector	Priority	Pending Flag	Enable Bit	Priority Bit
HWRST(eMMC)	0053h	1 (Highest)	hw_rst_pnd	IP.7	
SD CMD	0003h	2	SPND.0	IE.0	IP.0

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SD RPS	000Bh	3	SPND.1	IE.1	IP.1
SD DI	0013h	4	SPND.2	IE.2	IP.2
SD DO	001Bh	5	SPND.3	IE.3	IP.3
NAND Flash Controller	0023h	6	NTCTL1.7	IE.4	IP.4
BCH-Codec done	002Bh	7	BCTL0.7	IE.5	IP.5
BCH-Codec step1 done	0033h	8	BCTL1.7	IE.6	IE.6
IO wake up	003bh	9	EXINTR.3	IPE.0	IPE.4
Timer	0043h	10	TCTL.7	IPE.1	IPE.5
Serial Port	004Bh	11 (Lowest)	TCTL.3	IPE.2	IPE.6

6.3 Interrupt Latency

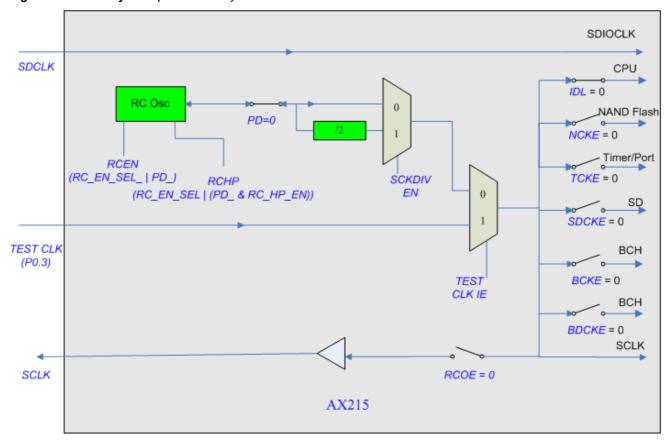
Interrupt response time depends on the state of the CPU when the interrupt occurs. Pending interrupts are sampled and priority decoded each system clock cycle. Therefore, the response time is 4–6 system clock cycles: 1 clock cycle to detect the interrupt, 2 clock cycles to back up the location of next instruction, and 1–3 clock cycles to complete the fetch and to execute the first instruction of ISR, depending on the instruction length. If an interrupt is pending when a RETI is executed, a single instruction is executed before serving the pending interrupt. Therefore, the maximum response time for an interrupt (when no other interrupt is currently being serviced or the new interrupt is of greater priority) occurs when the CPU is performing an RETI instruction followed by a 3-byte instruction as the next instruction. In this case, the response time is 10-12 system clock cycles: 1 clock cycle to detect the interrupt, 3 clock cycles to execute the RETI, 3 clock cycles to fetch and complete the following 3-byte instruction, 2 clock cycles to back up the location of next instruction and 1–3 clock cycles to complete the fetch the first instruction of ISR. If the CPU is executing an ISR for an interrupt with equal or higher priority, the new interrupt will not be serviced until the current ISR completes, including the RETI and following instruction.

7 Clocks and Reset Management

7.1 Clock System

AX215E possesses a configurable clock system aiming to provide balance between performance and power consumption in different applications. It provides fine-grain clock gating to shutdown unused part completely. The organization of clock system (default state) is illustrated in Figure 7-1.

Figure 7-1: Clock System (default state)



7.1.1 Clock Gating Control

There are 6 bits in PCTL to control the clock gating for the 6 main parts in AX215E, they are IDLE for CPU, TCKE for Timer, Serial Port and general IO, SDCKE for SD controller, NCKE for NAND Flash controller, BCKE and BDCKE for BCH-Codec. PD and HPEN is the performance control bit of RC oscillator, and PD is also the output control bit of RC oscillator.

Idle Mode:

Setting IDLE will force the CPU into a idle mode, CPU stops running instruction until any interrupts happen (EA = 1 is must). The interrupt will wake up the CPU and CPU will go to the ISR of this interrupt source.

Power Down Mode:

Power down mode aggressively turn the RC oscillator to low power mode and gate the output (RC oscillator is the global clock of the whole system). At this moment, there is no activity in any module extra RC oscillator. Only SD interrupt can resume the clocks and deactivate power down mode. There are 2 signals can wake up the system during power down mode, they are SDCMD and SDCLK.

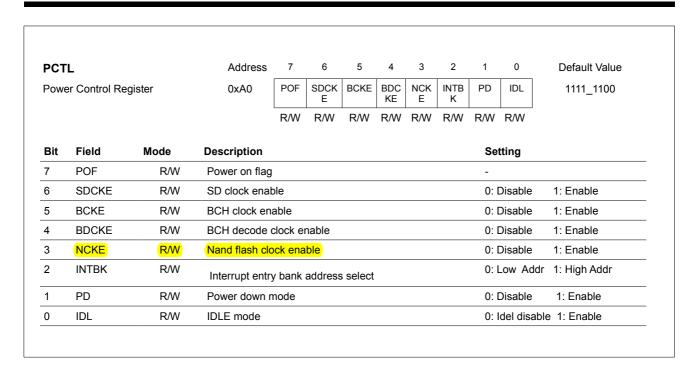
When wake up function is enabled before power down, any falling edge occurred on the selected signal will re-enable the oscillator and then the system is waken up. CPU will go to the ISR if PIE is enable, otherwise CPU goes on running the next instruction before power down. Before power down, it's recommended that all the ports are output high to void the floating leakage. To enable the wake up function, the operation steps listed below are recommended:

```
//select wake up pin and trigger edge
ORL CCTL, #0x40
//enable wake up function
ORL PCTL, #0x10
//insert 4 cycles delay
NOP
NOP
NOP
NOP
//clear wake up pending
ANL PCTL, #0x7F
//insert 4 cycles delay
NOP
NOP
NOP
NOP
//enable port wake up interrupt if needed
ORL IE1, #0x01
ORL IE, #0x81
```

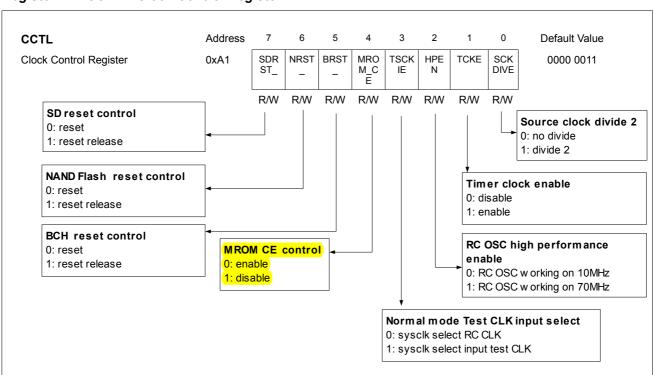
7.2 Relative Registers

Register 7-1: PCTL – Power Control Register

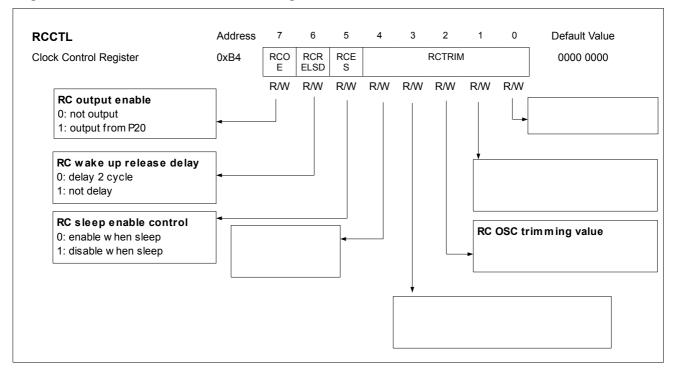
AX215E SD Card Controller INTERNAL DESIGN SPECIFICATION



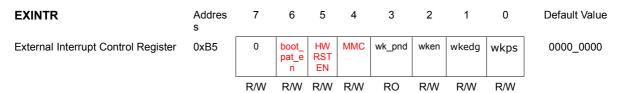
Register 7-2: CCTL - Clock Control Register







Register 7-4: EXINTR - External Interrupt Control Register



boot_pat_en: boot_pattern enable bit

0 : boot pattern disable.1 : boot pattern enable.

HWRSTEN: eMMC Host hardware reset enable

0 = disable

1 = enable

MMC: MMC device

0 = SD

1 = MMC

(NOTE: EXINTR 【4】和SD模块的BOOT_CFG【7】的区别,BOOT_CFG【7】(MMC_SD只读)为上电硬件检测MMC/SD信息,若上电后硬件检测到为0,表示为MMCdevice,需要把EXINTR【4】一直设为1,否则不需要。)

wk_pnd: wake up pending wken: wake up enable

0: unable 1:enable

wkedg: wake up pin edge select

0: rise edge1: fall edge

wkps: wake up pin select

0: SD clk pin

1: SD Command pin

7.3 Reset System

Only POR (power on reset) will reset the whole system of AX215E. It's illustrated in Figure 6-2.

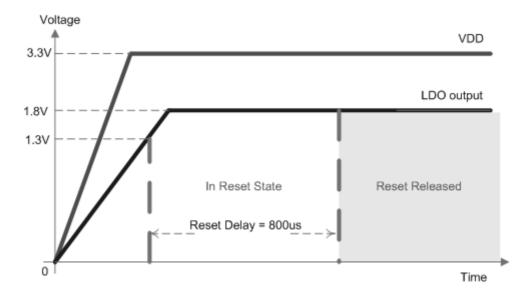


Figure 6-2: Reset Timing

8 Ports

AX215E has 52 IO pins. Figure 7-1 shows the structure of the IO.

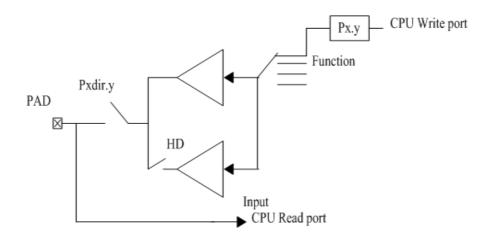


Figure 7-1: IO Structure

From Figure 7-1, user can see that you can set the port current driven strength, CPU will not have the correct value when read the port immediately after port register changed because the delay of synchronizer. Thus in this situation, 3 or more cycles delay should be inserted during write and read ports as the example codes shown below:

```
//configure the port's direction
//P1.7-4 output
//P1.3-0 input

MOV P1DIR, #0x0f
//write the value for output
//the value of port output buffer is 0x70

MOV P1, #0x70
//change the output
```

//the value of P1.3~0 output buffer are unknown because it is changed by ORL, CPU calculates the value read from port pin and then write the result back to port output buffer.

ORL P1, #0x10

//inserts 3 or more cycles delay if read is need

NOP

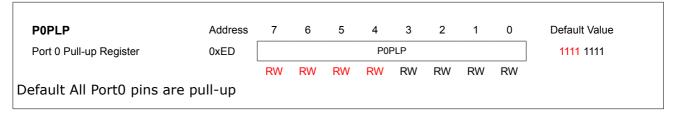
NOP

NOP

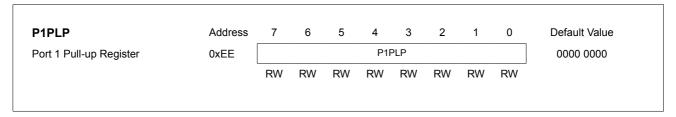
//read port

MOV A, P1

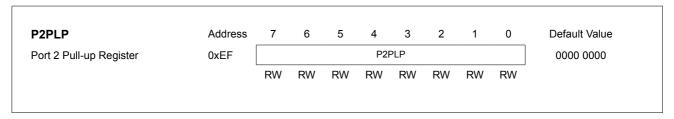
Register 8-1: P0PLP - Port 0 Pull-up Register



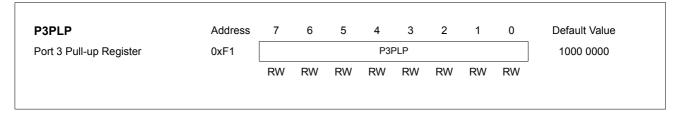
Register 8-2: P1PLP - Port 1 Pull-up Register



Register 8-3: P2PLP - Port 2 Pull-up Register



Register 8-4: P3PLP - Port 3 Pull-up Register



Register 8-5: P4PLP - Port 4 Pull-up Register

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P4PLP Default Value Address 7 6 5 3 1 0 Port 4 Pull-up Register 0xF2 0 P4PLP 0010 0000 RW RW RW RW

P4plp[6]: uart output port select

0: uart output from NCE2

1: uart output from SDDAT2

Register 8-6: P0 – Port 0 Register

P0	Address	7	6	5	4	3	2	1	0	Default Value
Port 0 Register	0xF3				Р	0				xxxx xxxx
		RW								

P0[7]: MMCDATA[7]

P0[6]:MMCDATA[6]

P0[5]:MMCDATA[5]

P0[4]:MMCDATA[4]

Register 8-7: P1 - Port 1 Register

P1 Port 1 Register	Address 0xF4	7	6	5	4 P		2	1	0	Default Value
	,	RW	RW	RW	RW	RW	RW	RW	RW	

Register 8-8: P2 – Port 2 Register

P2 Port 2 Register	Address 0xF5	7	6	5	4 P		2	1	0	Default Value
		RW	RW	RW	RW	RW	RW	RW	RW	

Register 8-9: P3 - Port 3 Register

P3	Address	7	6	5	4	3	2	1	0	Default Value
Port 3 Register	0xF6				F	3				0001 1000
	,	RW								



Register 8-10: P4 - Port 4 Register

P4	Address	7	6	5	4	3	2	1	0	Default Value
Port 4 Register	0xF7	0	0			Р	4			00xx xxxx
		RO								

P4[5]: SD_DAT[3]

P4[4]:SD_DAT[2]

P4[3]:SD_DAT[1]

P4[2]:SD_DAT[0]

P4[1]:SD_CMD

P4[0]:SD_CLK

Register 8-11: P0DIR - Port 0 Direction Register

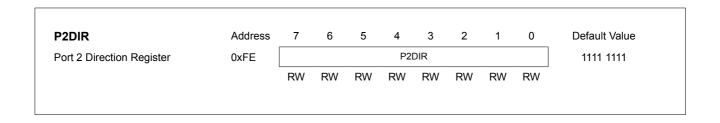
P0DIR Port 0 Direction Register	Address 0xFC	7	6	5		3 DIR	2	1	0	Default Value
		-	-	-	-	RW	RW	RW	RW	I

Register 8-12: P1DIR - Port 1 Direction Register

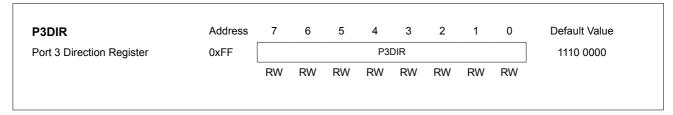
P1DIR	Address	7	6	5	4	3	2	1	0	Default Value
Port 1 Direction Register	0xFD				P11	DIR				1111 1111
		RW	RW	RW	RW	RW	RW	RW	RW	

Register 8-13: P2DIR - Port 2 Direction Register

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Register 8-14: P3DIR - Port 3 Direction Register



Register 8-15: P0HD – Port hard drive control

P0HD	Address	7	6	5	4	3	2	1	0	Default Value
Port 0 hard drive control Register	0xBC				P0	HD				0000 0000
		RW	•							

P0xHD: P0x hard drive control

0: Hard drive disable;

1: Hard drive enable;

Register 8-16: P1HD - Port1 hard drive control

P1HD	Address	7	6	5	4	3	2	1	0	Default Value
Port 1 hard drive control Register	0xBB				P1	HD				0000 0000
	·				R'	W				

P1xHD: P1x hard drive control

0: Hard drive disable;

1: Hard drive enable;

Register 8-17: P2HD - Port2 hard drive control

P2HD	Address	7	6	5	4	3	2	1	0	Default Value
Port 2 hard drive control Register	0xBA				P2	HD				0000 0000
					R'	W				

P2xHD: P2x hard drive control

0: Hard drive disable;

1: Hard drive enable;

Register 8-18: P3HD - Port3 hard drive control

	•	5	4	3	2	1	0	Default Value
38	P3HD 0000 0							
			R\	N				
3	8	8	8		8 P3HD RW			

P3xHD: P3x hard drive control

0: Hard drive disable;

1: Hard drive enable;

Register 8-19: P4HD - Port4 hard drive control



P4xHD: P4x hard drive control

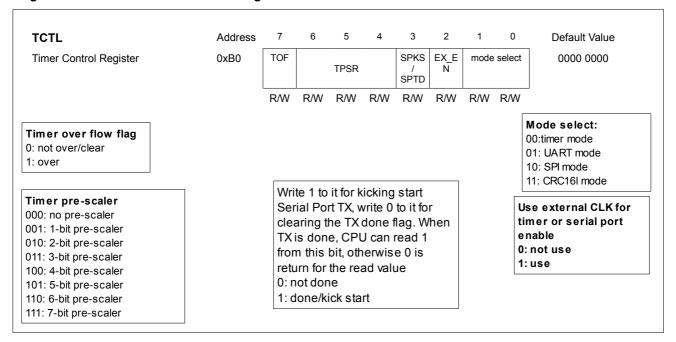
0: Hard drive disable;

1: Hard drive enable;

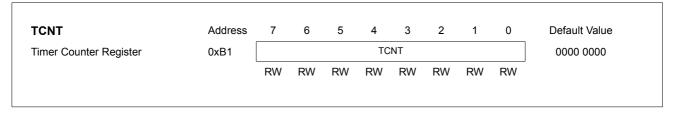
9 Timer and Serial Port

9.1 Timer and Serial Port Register

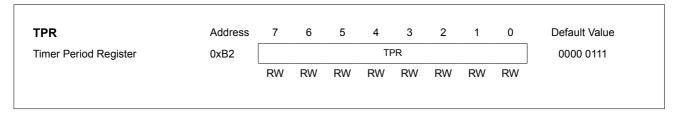
Register 9-1: TCTL - Timer Control Register



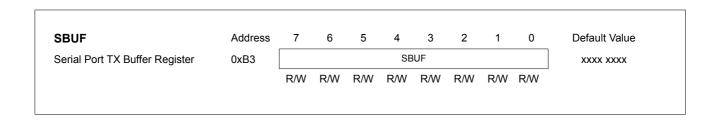
Register 9-2: TCNT - Timer Counter Register



Register 9-3: TPR - Timer Period Register



Register 9-4: SBUF – Serial Port RX/TX Buffer Register



9.2 Timer

The timer is a 8-bit system clock base timer with configurable 7-bit pre-scaler and period register. This timer can be used as a timer or the baud rate generator of serial port. Its block diagram is illustrated in Figure 8-1.

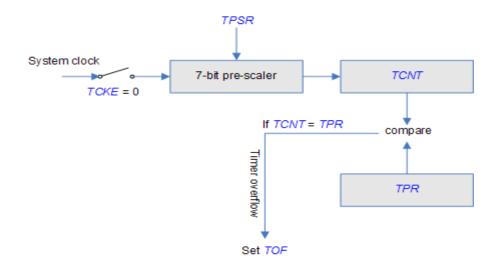


Figure 8-1: Timer Block Diagram

The Timer overflow rate calculation is :

Overflow Rate = TPSR*(TPR+1)

To enable the timer, it's recommended to follow the example code list below:

//enable the clock to timer

ORL CCTL, #0x02

//select pre-scaler 7-bit mode

MOV TCTL, #0x70

//configure the period register

MOV TPR, #0xFF

//clear the timer counter

MOV TCNT, #0x00

//clear the timer over flow flag CLR TOF //check the timer over flow flag JNB TOF, \$

9.3 **Uart Mode**

The serial port can be used to transmit data in UART protocol. It's a timer base serial port. The timing waveform is shown in Figure 8-2.

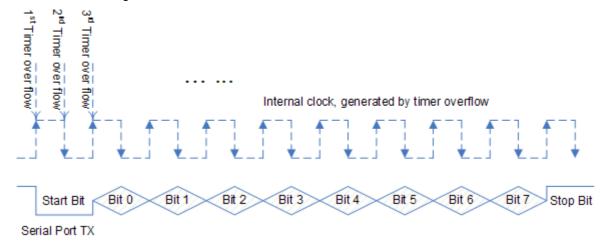


Figure 8-2: Serial Port UART TX Timing

The Serial Port TX/RX is MUXed with pin NCE2. The the baud rate calculation is:

Baud Rate = 2*(Overflow Rate)=2*TPSR*(TPR+1)



Note: UART MODE 有两组io输出, NCE2_(P02)和SDDAT2(P44)。通过配置寄存器 P4plp[6]: uart output port select, 0: uart output from NCE2; 1: uart output from SDDAT2.

Operation example code listed below:

MOV TCTL, #0x01 //configure the period register MOV TPR, #0x03 //write the data to be send in serial port buffer

MOV SBUF, #0xAA

//select UART mode

//kick start the TX

SETB SPKS

//wait the TX done flag be set

JNB SPTD, \$

//clear the TX done flag

CLR SPTD

9.4 SPI Mode

The serial port can be used to transmit data in SPI protocol. It's a timer base serial port. The timing waveform is shown in Figure 8-2.

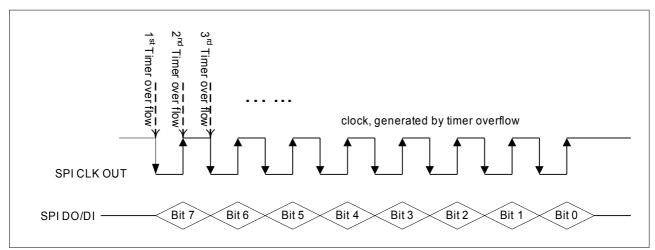


Figure 8-2: Serial Port SPI TX/RX Timing

The SPI TX is MUXed with pin NALE. The SPI RX is MUXed with pin NWP. The SPI CLK is MUXed with pin NCLE. The SPI CLK period calculation is:

SPI CLK period = 2*(Overflow Rate)=2*TPSR*(TPR+1)

Operation example code listed below:

//select SPI mode

MOV TCTL, #0x02

//configure the period register

MOV TPR, #0x03

//write the data to be send in serial port buffer

MOV SBUF, #0xAA

//kick start the TX/RX

SETB SPKS

//wait the TX/RX done flag be set

JNB SPTD, \$

//read RX data

MOV A, SBUF

//clear the TX/RX done flag

CLR SPTD

9.5 CRC16 Mode

Operation example code listed below:

//enable the clock to timer

ORL CCTL, #0x02

//select CRC16 mode

MOV TCTL, #0x03

//clear CRC16 Low buffer

MOV TCNT, #0x00

//clear CRC16 High buffer

MOV TPR, #0x00

//CRC16

MOV SBUF, #0x13

NOP

//read CRC16 Result

MOV A, TCNT

MOV A, TPR

10 NAND Flash Controller

The NAND Flash controller supports Configurable User Define Protocol for NAND Flash accessing.

10.1 NAND Flash Controller Register

Register 10-1: NFIFO0 - NAND Flash FIFO 0 Register

NFIFO0 NAND Flash FLFO 0 Register	Address 0x9B	7	6	5	4 NFI	3 FO0	2	1	0	Default Value
WAND Hashii Er o' o' Negistei	OXOD	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	3000 0000
NFIFO is the FIFO to store the NAND Flash command0, address data which will be sent. NFIFO0 has no default value, thus it should be initialized before using.										

Register 10-2: NFIFO1 - NAND Flash FIFO 1 Register

NFIFO1 NAND Flash FLFO 1 Register	Address 0x9C	7	6	5	4	3 FO1	2	1	0	Default Value
NAND Flash FLFO T Register	0x9C	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	0000 0000
NFIFO is the FIFO to store the N thus it should be initialized before		comma	ınd0, a	addres	s data	which	will be	sent.	NFIFO	1 has no default value,

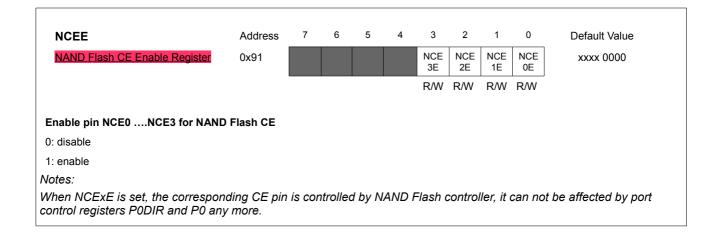
Register 10-3: NFIFO2 - NAND Flash FIFO 2 Register

NFIFO2	Address	7	6	5			2	1	0	Default Value
NAND Flash FLFO 2 Register	0x9D	R/W	R/W	R/W	R/W	FO2 R/W	R/W	R/W	R/W	0000 0000
NFIFO is the FIFO to store the NAND Flash command0, address data which will be sent. NFIFO2 has no default value, thus it should be initialized before using.										

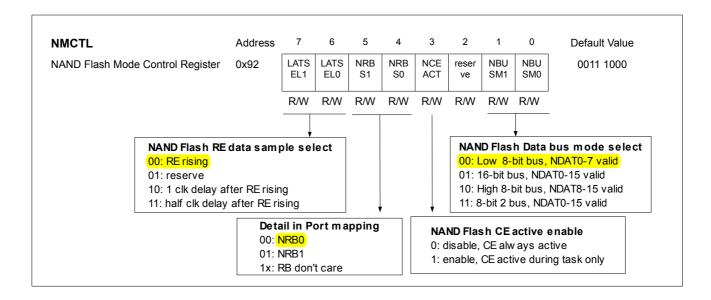
Register 10-4: NFIFO3 - NAND Flash FIFO 3 Register

NFIFO3	Address	7	6	5	4	3	2	1	0	Default Value
III II 00										1
NAND Flash FLFO 3 Register	0x9E	NFIFO3 0000 0000								
		R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	-
NFIFO is the FIFO to store the NAND Flash command0, address data which will be sent. NFIFO3 has no default value, thus it should be initialized before using.										

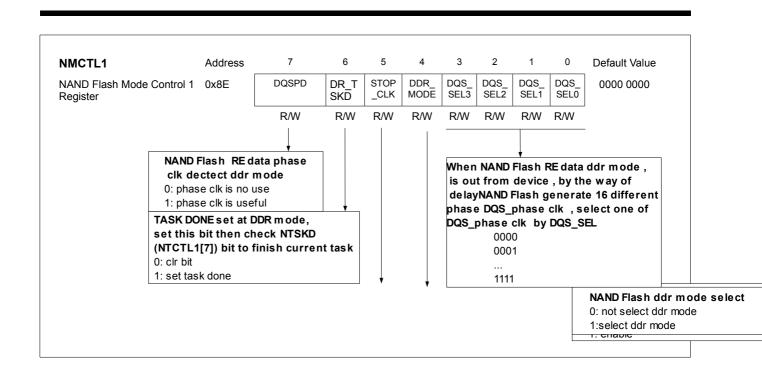
Register 10-5: NCEE – NAND Flash CE Enable Register



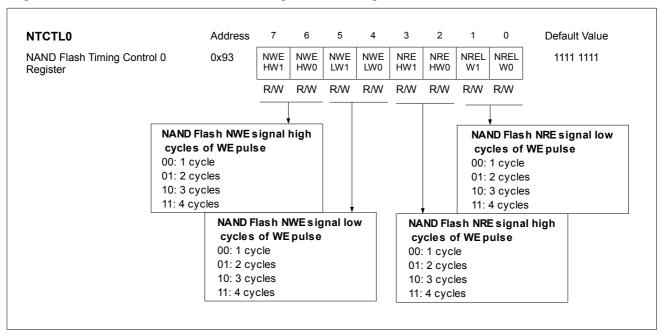
Register 10-6: NMCTL - NAND Flash Mode Control Register



Register 10-7: NMCTL1 - NAND Flash Mode Control 1 Register

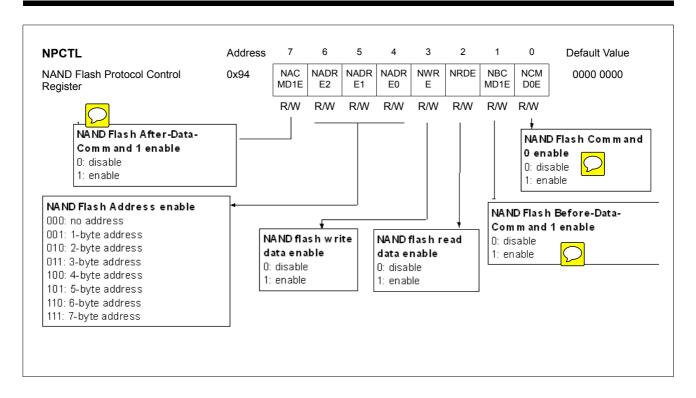


Register 10-8: NTCTL0 - NAND Flash Timing Control 0 Register

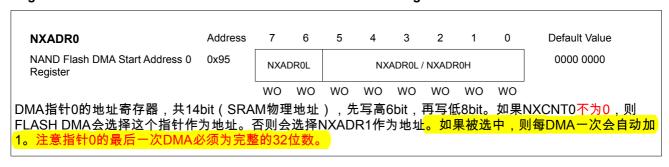


Register 10-9: NPCTL - NAND Flash Protocol Control Register

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Register 10-10: NXADR0 - NAND Flash DMA Start Address 0 Register



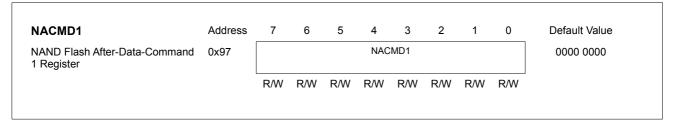
Register 10-11: NXCNT0 - NAND Flash DMA Start Address 0 Count



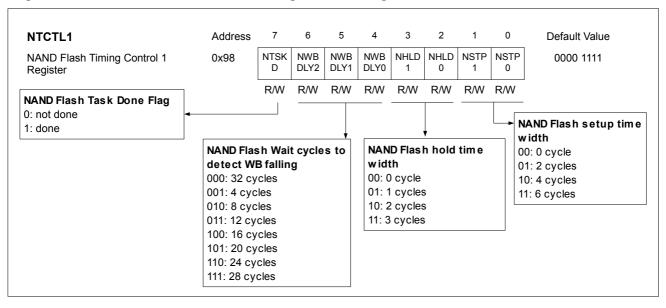
Register 10-12: NXADR1 - NAND Flash DMA Start Address 1 Register



Register 10-13: NACMD1 - NAND Flash After-Data-Command 1 Register

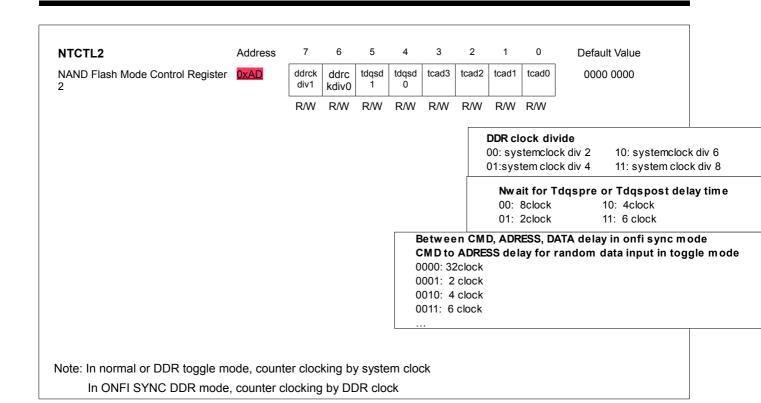


Register 10-14: NTCTL1 - NAND Flash Timing Control 1 Register



Register 10-15: NTCTL2 - NAND Flash Timing Control 1 Register 2

AX215E SD Card Controller INTERNAL DESIGN SPECIFICATION



Register 10-16: NPGSZ0 - NAND Flash Page Size 0 Register

NPGSZ0	Address	7	6	5	4	3	2	1	0	Default Value
NAND Flash Page Size 0 Register	0x99				NPG	SZ0				0000 0000
\bigcirc		W	W	W	W	W	W	W	W	

Register 10-17: NPGSZ1 – NAND Flash Page Size 1 Register

NPGSZ1	Address	7	6	5	4	3	2	1	0	Default Value
NAND Flash Page Size 1 Register	0x9A					NPG	00 0000			
	·	-	-	W	W	W	W	W	W	

10.2 Default State

To ensure the NAND Flash is in the right state after power up, the IO group of NAND Flash interface have a special state after reset:

Table 11-1: NAND Flash IO Default State

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Pin	State	Description
NCE0-3	Input With Pull-up at nomal mode	Do not select any flash
NDAT0-15	Input High Impedance	
NCLE	Output Low	Command disable
NALE	Output Low	Address disable
NRE	Output High	Read disable
NWE	Output High	Write disable
NWP	Output Low	Enable flash write protect mode
NRB0	Input High Impedance	NAND flash RB0 status input
NRB1	Input High Impedance	NAND flash RB1 status input
NDQS	Pin direction is control by ddr_mode	DQS input or output (used for DDR interface)

The NAND Flash is default in write protect state to prevent the error write operation during power up. The example codes of exiting write protect mode are listed below:

//exit the flash write protect mode

ORL P3, #0x01

10.3 User Define Protocol

The controller supports a flexible mode to accessing flash with the command and address organized by user configuration.

Table 11-2: NAND Flash controller mode configuration

Device support Mode	Bus mode	configuration
Support toggle ddr flash device	Low 8_bit mode	DDR_MODE =1 & nmctl[0] = 0
Support ONFI flash device work at sync mode	Low 8_bit mode	DDR_MODE =1 & nmctl[0] = 1
	Low 8_bit mode	DDR_MODE =0 & nmctl[1:0] = 2'b00
Support tradition flash device	16bit mode	DDR_MODE =0 & nmctl[1:0] = 2'b01
(include ONFI flash work at async	High 8_bit mode	DDR_MODE =0 & nmctl[1:0] = 2'b10
mode)	2-8bit mode	DDR_MODE =0 & nmctl[1:0] = 2'b11

Figure 10-1~ 10-6show the command format.

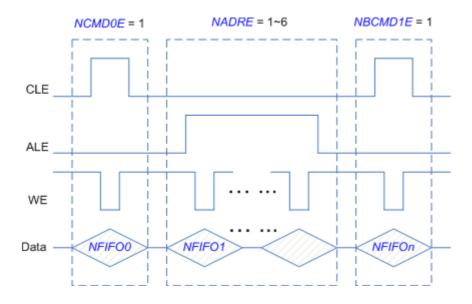


Figure 10-1: User Define Command & Address Part Format

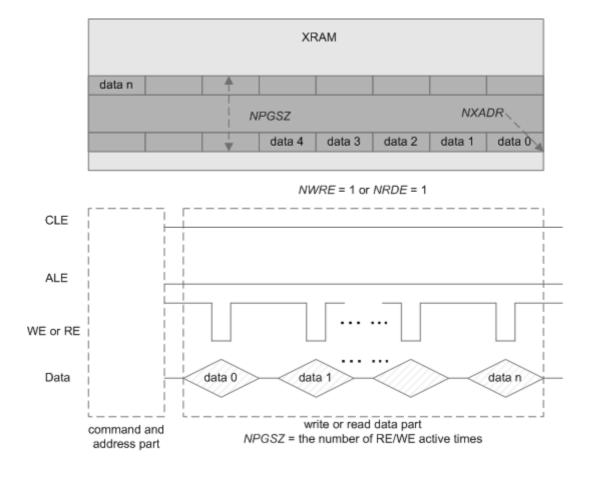


Figure 10-2: User Define Data Part Format

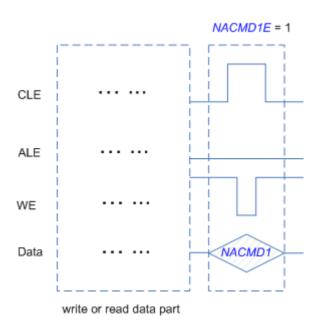


Figure 10-3: User Define Command1 Part Format

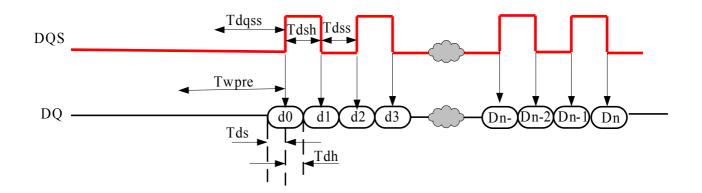


Figure 10-4:User Define write data to device at ddr mode

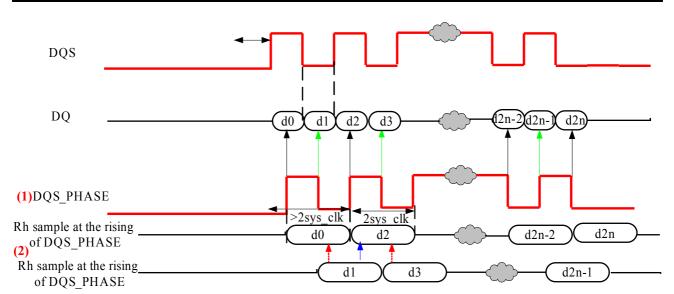


Figure 10-5:User Define read data from device at ddr mode

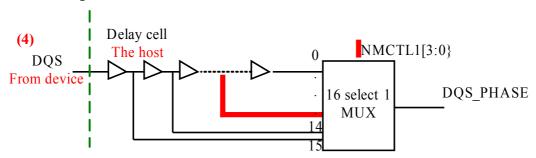


Figure 10-6:User Define DQS phase clk at ddr mode

In the command part, NBCMD1E and NACMD1E should not be enabled both. In the data part, NWRE and NRDE should not be enabled both.

10.4 Cycle Timing

The timing of flash IO pins are controlled by the flash timing control register NTCTL0 and NTCTL1. Figure 10- $7 \sim 10-12$ illustrate these timing waveform below.

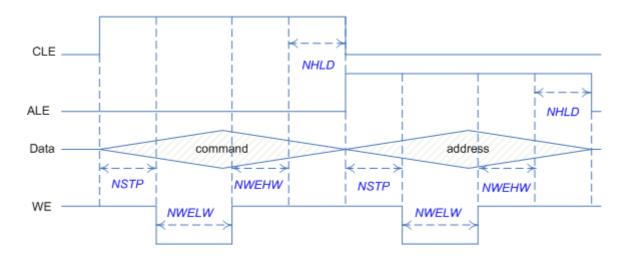


Figure 10-7: CLE / ALE Timing

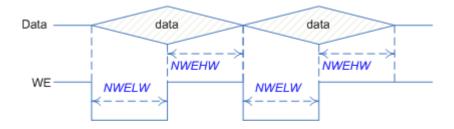


Figure 10-8: Write Data Timing

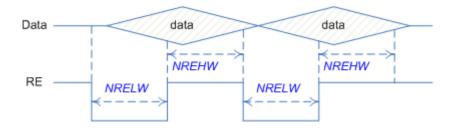


Figure 10-9: Read Data Timing

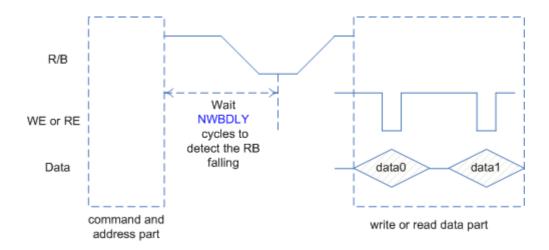


Figure 10-10: Wait R/B Falling Timing 1

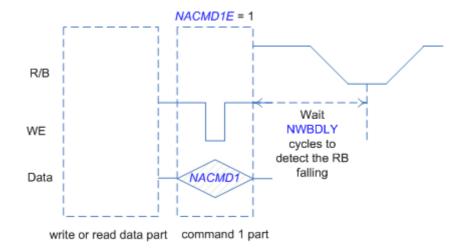


Figure 10-11: Wait R/B Falling Timing 2

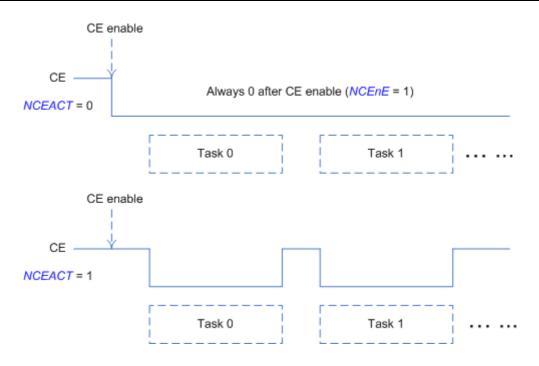


Figure 10-12: CE Timing

firgure 9-11 NRE out

firgure 9-12 NWE out

firgure 9-13 read data sample timing

10.5 Operation Flow

Before operating the NAND Flash controller to access the flash, the IOs connected to flash must be configured:

```
#define NFIFO4 NFIFO0
#define NFIFO5 NFIFO1
#define NFIFO6 NFIFO2
#define NFIFO7 NFIFO3
//initial the IO
MOV P3PLP, #0x20
MOV P3, #0x18
...
...
```

The 2nd step is to enable the NAND Flash controller's clock if needed:

ORL PCTL, #0x08

MOV NPGSZ0, #0x10 MOV NPGSZ1, #0x00

```
Then release the NAND Flash controller's reset:
ORL CCTL, #0x40
Configure the operation mode and cycle timing (please reference to the NAND Flash's data sheet):
//select bus mode (low 8-bit )
//enable CE active mode
//select RB0
MOV NMCTL, #0x08
//select timing
MOV NTCTLO, #0xFF
MOV NTCTL1, #0x7F
//select NCE0 enable
MOV NCEE, #0x01
When all the initialization above are done, the controller is ready for real accessing task. Accessing flash
examples:
RESET Task
//command 0 = 0xFF(Reset)
MOV NFIFO0, #0xFF
//enable command 0 only, kick-start the task
MOV NPCTL, #0x01
//wait task done
JNB NTSKD, $
//clear task done flag
CLR NTSK
READ STATUS Task
//不使用NXADRO,全部通过NXADR1来完成DMA
//configure DMA start address1 (0x4000)
// xram_start_addr1 = \{0x10, 0x00, 2'b00\};
MOV NXCNTO, #0X00//如果可以确保上次NXCNTO已经为0时,可以省略这两步
MOV NXCNTO, #0X00
MOV NXADR1, #0x10
MOV NXADR1, #0x00
//configure the number of read byte (0x0010)
```

```
//command 0 = 0x70(Read Status)
MOV NFIFO0, #0x70
//enable command 0 and read, kick-start the task
MOV NPCTL, #0x05
//wait task done
JNB NTSKD, $
//read the status value
//read data from sram
//clear task done flag
CLR NTSK
BLOCK ERASE Task
//command 1 = 0xD0 (start erase)
MOV NFIFO4, #0xD0
//address = 0x030201 (3 byte address)
MOV NFIFO3, #0x03 // third address
MOV NFIFO2, #0x02 // second address
MOV NFIFO1, #0x01 // first address
//command 0 = 0x60 (block erase)
MOV NFIFO0, #0x60
//enable command 0, address (3 byte) and before-data-command 1, kick-start the task
MOV NPCTL, #0x33
//wait task done
JNB NTSKD, $
//clear task done flag
CLR NTSK
PAGE PROGRAM Task
//configure the page size (4K data)
MOV NPGSZ0, #0x00
MOV NPGSZ1, #0x10
//configure the data buffer start address in XRAM, the data should be ready in the buffer
// xram_start_addr0 = \{0x04, 0x00, 2'b00\};
```

```
// xram_start_addr1 = \{0x06, 0x00, 2'b00\};
//当addr0 完成0x200次DMA(32bit,即2K Byte)后会指向 xram_start_addr1完成剩下的DMA。
MOV NXADRO, #0x04
MOV NXADRO, #0x00
MOV NXCNTO, #0X02
MOV NXCNTO, #0X00
MOV NXADR1, #0x06
MOV NXADR1, #0x00
//address = 0x00_02_00_00_00 (5 byte)
MOV NFIFO5, #0x00
MOV NFIFO4, #0x02
MOV NFIFO3, #0x00
MOV NFIFO2, #0x00
MOV NFIFO1, #0x00
//command 0 = 0x80 (page program)
MOV NFIFO0, #0x80
//command 1 = 0x10 (start program)
MOV NACMD1, #0x10
//enable command 0, address (5 byte), write and after-data-command 1, kick-start the task
MOV NPCTL, #0xD9
//wait task done
JNB NTSKD, $
//clear task done flag
CLR NTSK
PAGE READ Task
//configure the page size (4K data)
MOV NPGSZ0, #0x00
MOV NPGSZ1, #0x10
//configure the data buffer start address in XRAM
// xram_start_addr1 = \{0x04, 0x00, 2'b00\};
//因为NXCNTO为0,所以会一直使用 xram_start_addr1完成DMA。
MOV NXCNTO, #0X00
MOV NXCNTO, #0X00
MOV NXADR1, #0x04
MOV NXADR1, #0x00
```

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```
//command 1 = 0x30 (start read)
MOV NFIFO6, #0x30
//address = 0x00, 0x02, 0x00, 0x00, 0x00 (5 byte)
MOV NFIFO5, #0x00
MOV NFIFO4, #0x02
MOV NFIFO3, #0x00
MOV NFIFO2, #0x00
MOV NFIFO1, #0x00
//command 0 = 0x00 (page read)
MOV NFIFO0, #0x00
//enable command 0, address (5 byte), read and before-data-command 1, kick-start the task
MOV NPCTL, #0x57
//wait task done
JNB NTSKD, $
//read the data from the data buffer
//clear task done flag
CLR NTSK
```

STOP NAND FLASH Task

```
//set task done flag
SETB NTSK
NOP
NOP
//clear task done flag
CLR NTSK
```

WRITE CMD0 and ADDRESS ONLY Task

```
//address = 0x00_02_00_00_00 (5 byte)

MOV NFIFO5, #0x00

MOV NFIFO4, #0x02

MOV NFIFO3, #0x00

MOV NFIFO2, #0x00

MOV NFIFO1, #0x00

//command 0 = 0x80 (page program)

MOV NFIFO0, #0x80
```

```
//enable command 0, address (5 byte), kick-start the task MOV NPCTL, #0x51
//wait task done
JNB NTSKD, $
//clear task done flag
CLR NTSK
```

WRITE DATA ONLY Task

```
/enable write data, kick-start the task MOV NPCTL, #0x08

//wait task done

JNB NTSKD, $

//clear task done flag

CLR NTSK
```

WRITE CMD1 ONLY Task

```
//command 1 = 0x10 (start program)
MOV NACMD1, #0x10

//enable CMD1, kick-start the task
MOV NPCTL, #0x81

//wait task done

JNB NTSKD, $

//clear task done flag

CLR NTSK
```

If the NAND Flash controller interrupt is enable (IE.4= 1), an interrupt is generated when task is done (NTSKD = 1).

2. operate follow for device ddr mode (including toggle ddr and ONFI source synchronous mode)

(1)toggle ddr mode

Before operating the NAND Flash controller to access the flash, the IOs connected to flash must be configured:

```
#define NFIFO4 NFIFO0
#define NFIFO5 NFIFO1
#define NFIFO6 NFIFO2
#define NFIFO7 NFIFO3
//initial the IO
MOV P3PLP, #0x20
```

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```
ORL P3DIR, #0x20
The 2nd step is to enable the NAND Flash controller's clock if needed:
ORL PCTL, #0x08
Then release the NAND Flash controller's reset:
ORL CCTL, #0x40
Configure the operation mode and cycle timing (please reference to the toggle ddr Flash's data sheet ):
//select bus mode (low 8-bit & toggle ddr mode )
//enable CE active mode
//select RB0
MOV NMCTL, #0x08
MOV NMCTL1, #0X10
//select timing
MOV NTCTLO, #0xFF
MOV NTCTL1, #0x7F
MOV NTCTL2, #0x3f
//select NCE0 enable
MOV NCEE, #0x01
    When all the initialization above are done, the controller is ready for real accessing task. Accessing flash
```

RESET Task

examples:

```
//command 0 = 0xFF(Reset)

MOV NFIFO0, #0xFF

//enable command 0 only, kick-start the task

MOV NPCTL, #0x01

//wait task done

JNB NTSKD, $

//clear task done flag

CLR NTSK
```

DQS phase clk select Task

```
//before read device ,we need select a good DQS phase clk to sample data MOV R0 , \#0x00
```

```
MOV R1, #0x10 // DQS_SEL= nmctl[3:0]
sel_phase_clk:
                               //change the DQS_SEL , select ddr mode
     MOV NMCTL1, R0
           NMCTL1, \#(0x01 << 4)
     ORL
     LCALL
               read_task
                               //a read task ,after task done
// check DQS phase clk pending bit , when detect nmctl[7] = 0 , DQS phase select done
     MOV A, NMCTL1
     ANL A, #0x80
     JZ get phase clk
                               // if nmctl[7] = 1 , change DQS_SEL
     INC
            R0
     DJNZ R1, sel_phase_clk
get_phase_clk:
     MOV A , R0
                            //get the useful DQS phase clk number ,when nmctl1[7]=0
 //divide 2 : DQS_SEL=0000,...,r0, detect a good DQS phase clk , so DQS_SEL= r0 /2
     RR
     ANL A , #~0x80
     MOV NMCTL1, A
     ORL NMCTL1, \#(0x01 < <4) //set the right dqs phase clk, select DDR mode
   after get the right DQS phase clk ,the page read write task , cmd and adress task are the same as above
    tradiction flash's
   ......
```

(2) ONFI source synchronous mode

Before operating the NAND Flash controller to access the flash, the IOs connected to flash must be configured:

```
#define NFIFO4 NFIFO0
#define NFIFO5 NFIFO1
#define NFIFO6 NFIFO2
#define NFIFO7 NFIFO3
//initial the IO
MOV P3PLP, #0x20
ORL P3DIR, #0x20
```

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```
The 2nd step is to enable the NAND Flash controller's clock if needed:
ORL PCTL, #0x08
Then release the NAND Flash controller's reset:
ORL CCTL, #0x40
RESET Task
//command 0 = 0xFF(Reset)
MOV NFIFOO, #0xFF
//enable command 0 only, kick-start the task
MOV NPCTL, #0x01
//wait task done
JNB NTSKD, $
//clear task done flag
   CLR NTSK
select ONFI synchronous mode
//set ONFI feature , please reference to the ONFI data sheet
MOV NPGSZ0 , #0X04
                         ;4 parameters
MOV NPGSZ1 , #0X00
;org 0x200 (0x11 ,0x00,0x00,0x00 )4 byte data as parameters
MOV NXCNTO, #0X00
MOV NXCNTO, #0X00
MOV NXADR1, #0x02
MOV NXADR1, #0x00
MOV NFIFOO , #0XEF ; CMD
MOV NFIFO1 , #0X01
                       ; ADR
MOV NPCTL , #0X19
//wait task done
JNB NTSKD, $
//clear task done flag
   CLR NTSK
```

//select bus mode (low 8-bit & onfi ddr mode)

```
//enable CE active mode
//select RB0
MOV NMCTL, #0x09
MOV NMCTL1, #0X10
//select timing
MOV NTCTLO, #0xFF
MOV NTCTL1, #0x7F
MOV NTCTL2, #0x3f
//select NCE0 enable
MOV NCEE, #0x01
DQS phase clk select Task
 //before read device ,we need select a good DQS phase clk to sample data
 MOV R0, #0x00
 MOV R1, #0x10 // DQS_SEL= nmctl[3:0]
sel_phase_clk:
                              //change the DQS_SEL , select ddr mode
     MOV NMCTL1, R0
     ORL NMCTL1, \#(0x01 << 4)
     LCALL
               read_task
                              //a read task ,after task done
// check DQS phase clk pending bit , when detect nmctl[7] = 0 , DQS phase select done
     MOV A, NMCTL1
     ANL A, #0x80
     JZ get_phase_clk
                              // if nmctl[7] = 1 , change DQS_SEL
     INC
           R0
     DJNZ R1 , sel_phase_clk
get_phase_clk:
     MOV A , RO
                            //get the useful DQS phase clk number ,when nmctl1[7]=0
 //divide 2 : DQS_SEL=0000,...,r0, detect a good DQS phase clk , so DQS_SEL= r0 /2
     RR A
     ANL A , #~0x80
     MOV NMCTL1, A
     ORL NMCTL1, #(0x01<<4) //set the right dqs phase clk, select DDR mode
   after get the right DQS phase clk ,the page read write task , cmd and adress task are the same as above
```

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10.6 Packet size setting

NAND FLASH Controller can work on 8-bit or 16-bit data bus mode. It is different setting from 8-bit mode to 16-bit mode.

When read/write n byte work on 8-bit data bus mode, packet size set n.

```
//configure the number of read/write byte (if n = 0x0110) 

MOV\ NPGSZ0,\ \#0x10 

MOV\ NPGSZ1,\ \#0x01 

When read/write n word work on 16-bit data bus mode, packet size set (2*n - 1). 

//configure the number of read/write byte (if n = 0x0110, (2*n - 1) = 0x021f)
```

MOV NPGSZ0, #0x1f

MOV NPGSZ1, #0x02

11 bad column management

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BCMADDR

Position	7	6	5	4	3	2	1	0
Name		BCMA	DDRL			BCMA BCMA		
Default	X	X	X	X	X	X	X	X
Access	W	W	W	W	W	W	W	W

BCMADDR: BCM begin address

这个寄存器在坏列管理模式时用于指定从memory的哪里开始取坏列地址,因为这个寄存器表示的是32X2048的memory的物理地址,又因为BCM用的是16bit的数,所以这个地址为12位。(地址范围为0X000~0XFFF,最低位表示用高16bit(1)还是低16bit(0))

操作这个寄存器需要写两次,第一次写高4bit,第二次写低8bit的地址;

BCMCTL

Position	7	6	5	4	3	2	1	0
Name								BCMEN
Default	0	0	0	0	0	0		0
Access								R/W

BCMEN: 坏列管理使能。注意不需要坏列管理时,这bit必须清零。

0: Disable1: Enable

BCMCNT

Position	7	6	5	4	3	2	1	0
Name				BCM	ICNT			
Default	X	X	X	X	X	X	X	X
Access	W	W	W	W	W	W	W	W

BCMCNT:该次操作中坏列的数量(需要减1,写0表示有1个坏列)。每出现一个坏列,BCMCNT会减1。如果BCMCNT已经为0,则再出现一个坏列后,BCMEN会disable。注意:当使能BCMEN时,flash controller中的NPGSZ必须加上这个CNT的值,例如原本NPGSZ是1024个byte,如果这次的坏列数量是4个坏列(即4byte),则NPGSZ的值要改为1028个byte,否则会有4个byte不会写到flash中。

BCMDATA

Position	7	6	5	4	3	2	1	0
Name				BCM	DATA			
Default	X	X	X	X	X	X	X	X
Access	W	W	W	W	W	W	W	W

BCMDATA: 将会被写入到坏列去的数据。

Operation Guide

Write bad column address (坏列地址写入)

如图1所示,坏列地址存储在一块32 X 2048的memory中,和XDATA空间中地址为0X8000~0X9FFF的memory为同一块memory。

当需要将坏列地址写进这个memory时,直接通过CPU写入即可。

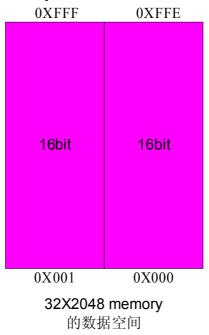


图1:存储坏列地址的memory的数据空间

其中每个16bit的格式如下:

Byte0		N	lot us	е					В	ad co	lumn a	addres	s			
BIT	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0

注意:这个坏列地址指的是该次操作中的第几个byte,例如往flash写数据,NF_CTL会自动通过DMA从SRAM拿数据,如果第三个byte将会被写入坏列中,则这个坏列地址必须写入2,这样原来的第3 byte就会被BCMDATA代替,第3byte会写进在下一个正常的flash空间中。16Bit和8x2 flash也一样,均是以byte为单位来表示坏列地址。

bad column manage (坏列管理)

坏列管理的主要运作方法如下:

(注意BCH的kick start必须放在以下步骤之前)

- 1.写入坏列地址,具体步骤见上,不需要更新坏列地址时可跳过这步;
- 2.指定从memory哪里开始读坏列地址;例如0x801为第一个坏列地址(对应的XDATA逻辑地址为((0X801 << 1) + 0X8000):

MOV BCMADDR, #0X08;

MOV BCMADDR, #0X01;

- 3.指定该次操作中坏列的数量,例如有10个坏列(需要减1): MOV BCMCNT, #0X09;
- 4.指定写入到坏列的数据:

MOV BCMDATA, #0XAA;

- 5.Enable bad column manage,选择读或者写flash;例如读flash; MOV BCMCTL, #0X03;
- 6.配置和kick start NFC;

7.等待NFC task done, disable BCM。

.....

MOV BCMCTL, #0X00;

执行过程为:

每次write flash时,会有一个计数器,每写1byte,计数器加1,然后将计数器的值与当前的坏列地址作比较,两者相等时则判断当前为坏列,这时则将BCMDATA的值替换掉原来的数据,原来的数据则顺延到下一次写。同时,从memory读出下一个坏列地址。

Read flash类似,遇到坏列地址时,会丢弃对应那byte。

完成一次连续的操作,计数器会清零。这时需要重新写BCM begin address和BCMCNT

0

12 **BCH-Codec**

The BCH-Codec supports 17/25/31/35/44-bit BCH encode/decode algorithms.

17-bit mode has 17 * 14 = 238 redundant bits = 29 Byte + 6bit.

25-bit mode has 25 * 14 = 350 redundant bits = 43 Byte + 6bit.

31-bit mode has 31 * 14 = 434 redundant bits = 54Byte + 2bit.

35-bit mode has 35 * 14 = 490 redundant bits = 61 Byte + 2bit. 44-bit mode has 44 * 14 = 616 redundant bits = 77 Byte + 0bit.

It is needed to release BCH reset in CCTL.5, enable bclk and bdclk (for decode mode) in PCTL before using this module.

BCH encode 和decode 的数据长度都是需要设置为8bit 的倍数,且encode 的长度+ 冗余数据长度 = decode 数据长度,当冗余长度不是8的倍数,又满足decode长度为8的倍数时,encode 数据长度不会是8 的倍数,此 时硬件会自动根据不同的bit mode 选择,填0以满足要求。

例如选择31 bit mode 时,冗余为 54Byte + 2bit,即encode 数据长度只能是整数byte + 6 bit data,这样 encode 的长度+ 冗余数据长度 = decode 数据长度 才满足8 bit 的倍数,此时硬件会自动在encode 时填入2 bit 0,以满足encode 数据需求

BCH Codec Register

Register 11-1: BXADR0 – BCH-Codec DMA Start Address 0 Register

BXADR0	Address	7	6	6	5	4	3	2	1	0	Default Value
BCH-Codec DMA Start Address 0 Register	0X86					ВХА	DR0				0000 0000
		W	٧	٧	W	W	W	W	W	W	

Note: BCH data buffer 0 DMA start address (from XRAM). Write 14bit address to this register twice, high 6 bit first, then low 8 bit. Start address is integer and divided 4 of XRAM physical address. Auto increase.

encode: DMA address from XRAM

decode: select data from XRAM: DMA address from SRAM

select data from NFC: no use

Register 11-2: BXADR1 – BCH-Codec DMA Start Address 1 Register

BXADR1	Address	7	6	5	4	3	2	1	0	Default Value
BCH-Codec DMA Start Address 1 Register	0X87				ВХА	DR1				0000 0000
		W	W	W	W	W	W	W	W	

Note: BCH data buffer 1 DMA start address (from XRAM). Write 14bit address to this register twice, high 6 bit first, then low 8 bit. Start address is integer and divided 4 of XRAM physical address. Auto increase.

encode: DMA address from XRAM

decode: select data from XRAM: DMA address from SRAM

select data from NFC: no use



BXADR2	Address	7	6	5	4	3	2	1	0	Default Value
BCH-Codec DMA Start Address 1 Register	Start Address 0X8B BXADR1								0000 0000	
		W	W	W	W	W	W	W	W	

For encode mode:

Write register only:

BCH redundant data DMA address to XRAM. Write 14bit address to this register twice, high 6 bit first, then low 8 bit. Start address is integer and divided 4 of XRAM physical address. Auto increase.

Encode 冗余数据处理:

- 1,直接写入flash mode 时,冗余数据直接送到flash controller,不保存
- 2,非写入flash mode 时,冗余数据保存到BXADR2 指向地址,可以通过CPU读取这些数据

For decode mode:

Read register only:

Indicate BCH error position data start address (base address is A000H): A000 + BXADR2:

decode 错误数据位置可以通过CPU读取,或使用硬件自动纠错模块处理数据

Register 11-2: BPSZ – BCH-Codec DMA DATA packet size Register

BPSZ	Address	7	6	5	4	3	2	1	0	Default Value
BCH-Codec data packet size	0X8D				BF	SZ				0000 0000
		W	W	W	W	W	W	W	W	

Note: BCH encode or decode data byte length packet size. Write 12bit counter to this register twice, high 4 bit first, then low 8 bit.

Encode mode: encode data 长度,以byte 为单位,剩余几bit不足1byte 的,硬件自动

根据不同的bit mode 填入相应的0来进行编码,所以要按足1 byte计算

Decode mode: decode data 长度,一定是整数byte data

Register 11-2: BCNT0 – BCH-Codec DMA DATA buffer 0 counter Register

BF0CNT	Address	7	6	5	4	3	2	1	0	Default Value
BCH-Codec data buffer0 CNT	0X8C				BF0	CNT				0000 0000
		W	W	W	W	W	W	W	W	

Note: BCH encode or decode data buffer0 byte counter. Write 10bit counter to this register twice, high 2 bit first, then low 8 bit.

设置要求:BFOCNT*4 <= BPSZ, BFOCNT为0 或需要的byte数除以4

当选择使用一个data buffer 时, BFOCNT =0;

当选择使用两个data buffer 时,BFOCNT 为data buffer 0 的数据长度,且数值是需要的byte数除以4。

Register 11-3: BCTLO - BCH-Codec Control O Register

BCTL0	Addres s	7	6	5	4	3	2	1	0	Default Value
BCH-Codec Control 0 Register	0X88	BDO NE	BFAI L	BHE RR	RDT DMA EN	rev	BTSI	EL		0000 0000
		R/W	R	R	R/W	R/W	R/W			

Bit	Field	Mode	Description	Setting
7	BDONE	R/W	BCH done flag	Read: 0: bch not done
				1: bch done
				Write: 0: clear bit
				1: no effect
6	BFAIL	RO	BCH fail	0: data correct-able
				1: data correct fail
5	BHERR	RO	BCH has error	0: BCH detect no error
				1: BCH detect error
4	RDTDMA	R/W	BCH redundant	0: BCH redundant bit not DMA to
	EN		decode DMA enable	SRAM
			enabre	1: BCH redundant bit DMA to SRAM
3	rev	R/W		
2:0	BTSEL	R/W	BCH correct	000: 17 bit
			bit select	001: 25 bit
				010: 31 bit
				011: 35 bit
				1xx: 44 bit

Note:

Register 11-4: BCTL1 – BCH-Codec Control 1 Register

BCTL1	Address	7	6	5	4	3	2	1	0	Default Value
BCH-Codec Control 1 Register	0X89	BSDONE	BDMAMUX	BDCSEL	BMODE	BEPA DRTG	-	-	BKS	0000 0000
		R/W	R/W	R/W	R/W	R/W	-	-	wo	

Bit	Field	Mode	Description	Setting
7	BSDONE	R/W	BCH syndrome done	Read: 0: bch syndrome not done 1: bch syndrome done Write: 0: clear bit 1: no effect
6	BDMAMU X	R/W	BCH data DMA select	Encode mode: 0: data from SRAM, redundant data save to SRAM 1: data from SRAM, encode data and redundant data save to NFC decode mode 0: data from SRAM, error position save to SRAM 1: data from NFC, error position save to SRAM
5	BDCSEL	R/W	BCH decode length select	0: 8864 1: 4768
4	BMODE	R/W	BCH mode	0: encode mode 1: decode mode
3	BEPADR TG	R/W	BCH error position buffer auto toggle	0: disable toggle, always use A000H buffer 1: enable toggle, auto loop from A000H, A0B0H; can be read low 8bit by bxadr2 in decode mode
2-1	_	_	_	_
0	BKS	WO	BCH kick start	0: no effect 1: kick start

Register 11-7: BECNT – BCH-Codec Error Counter Register

BECNT	Address	7	6	5	4	3	2	1	0	Default Value
BCH-Codec Error Counter Register	0X8A				XXXX XXXX					
		R	R	R	R	R	R	R	R	

Encode

To encode one package, it is needed to set as follows:

Encode and save redundant data to SRAM:

1, set DMA data buffer start address, redundant data DMA start address, buffer size

note: BECNT is validly respond to BFAIL = 0 and BHERR = 1.

2, set encode mode, data save to SRAM and select T(bit correction ability), initial packet size and data buffer0 counter(if using one data buffer, BF0CNT = 0), (BPSZ = encode byte)(eg. BPSZ = 1024 + 7, BF0CNT = 1024 (using two data buffer))

```
3, kick start encode
4, check done BCTL1.7
5, clear done
Example for encode:
// parameter define
#define ECBCHPSZ (1024 + 7)
#define BCHBF0CNT 1024
#define BCHBFXADR0 0x1000
#define BCHBFXADR1 0x5000
#define BCHBFXADR2 0x6000
#define TSEL 4
#define BL1K 0
// configure packet size, data buffer start address, buffer 0 counter
  MOV BPSZ,
                #high (ECBCHPSZ)
  MOV BPSZ.
                #low (ECBCHPSZ)
  MOV BF0CNT, #high (BCHBF0CNT>>2)
  MOV BF0CNT, #low (BCHBF0CNT>>2)
  MOV BXADR0, #high (BCHBFXADR0>>2)
  MOV BXADR0, #low (BCHBFXADR0>>2)
  MOV BXADR1, #high (BCHBFXADR1>>2)
  MOV BXADR1, #low (BCHBFXADR1>>2)
// redundant data write to SRAM start address
  MOV BXADR2, #high (BCHBFXADR2>>2)
  MOV BXADR2, #low (BCHBFXADR2>>2)
// select 44bit mode
  MOV BCTL0, #(TSEL<<0)
// select encode mode, 1K byte sector decode length, redundant data save to SRAM
  MOV BCTL1, #((0x00<<6) | (BL1K<<5) | (0x00<<4))
// kick start
  ORL BCTL1,#(0x01<<0)
// wait encode finish
  WAITD:
       MOV A, BCTL1
       JNB ACC.7, WAITD
//clear done
  ANL BCTL1,#~(0x01<<7)
  CLR BCTL0.7
```

Encode and save redundant data to NFC:

1, set DMA data buffer start address, redundant data DMA start address, buffer size

- 2, set encode mode, data save to NFC and select T(bit correction ability), initial packet size and data buffer0 counter(if using one data buffer, BF0CNT = 0), (BPSZ = encode byte)(eg. BPSZ = 1024 + 7, BF0CNT = 1024 (using two data buffer))
- 3, set NFC controller
- 4, kick start encode
- 5, check done BCTL1.7
- 6, clear done

Decode and correct data

Decode:

Decode one data packet from SRAM:

- 1, set DMA data start address, buffer size
- 2, set decode mode, data from SRAM and select T(bit correction ability), initial packet size and data buffer0 counter(if using one data buffer, BF0CNT = 0), (BPSZ = decode byte)(eg. BPSZ = 1024 + 7+77, BF0CNT = 1024 (using two data buffer), T = 44 bit mode)
- 3. kick start decode
- 4, check bchdone, and if there have errors, correct and clear bch syndrome done then bch done

Example for decode:

```
// configure packet size, data buffer start address, buffer 0 counter
                #high (ECBCHPSZ)
  MOV BPSZ,
                #low (ECBCHPSZ)
  MOV BPSZ.
  MOV BF0CNT, #high (BCHBF0CNT>>2)
  MOV BF0CNT, #low (BCHBF0CNT>>2)
  MOV BXADR0, #high (BCHBFXADR0>>2)
  MOV BXADR0, #low (BCHBFXADR0>>2)
  MOV BXADR1, #high (BCHBFXADR1>>2)
  MOV BXADR1, #low (BCHBFXADR1>>2)
// select 44bit mode
  MOV BCTL0, #(TSEL<<0)
// select decode mode, 1K byte sector decode length, redundant data save to SRAM
  MOV BCTL1, #((0x00<<6) | (BL1K<<5) | (0x01<<4))
// kick start
  ORL BCTL1,#(0x01<<0)
// wait decode stage1 finish
  WAITSD:
       MOV A, BCTL1
       JNB ACC.7, WAITSD
// wait decode finish
  WAITD:
       JNB BCTL0.7, WAITD
// check error flag
  CALL CHECKERR
//clear stage 1 done
  ANL BCTL1,#~(0x01<<7)
//clear BCH done
  CLR BCTL0.7
```

Decode one data packet from NFC:

- 1, set DMA data start address, buffer size
- 2, set decode mode, data from NFC and select T(bit correction ability), initial packet size and data buffer0 counter(if using one data buffer, BF0CNT = 0), (BPSZ = decode byte)(eg. BPSZ = 1024 + 7+77, BF0CNT = 1024 (using two data buffer),T = 44 bit mode)
- 3, kick start decode
- 4, check behadone, and if there have errors, correct and clear beh syndrome done then beh done

Decode several data packets:

- 1, set DMA data start address, buffer size
- 2, set decode mode, data from SRAM and select T(bit correction ability), initial packet size and data buffer0 counter(if using one data buffer, BF0CNT = 0), (BPSZ = decode byte)(eg. BPSZ = 1024 + 7+77, BF0CNT = 1024 (using two data buffer), T = 44 bit mode)
- 3, kick start 1st decode
- 4, wait bch 1st syndrome done, if done, reconfigure DMA address ect. Then kick start 2nd decode. Repeat step 4 one more time (wait bch 2nd syndrome done, and kick start 3rd decode)
- 5, check behdone (first time for 1st data packet), and if there have errors, correct and clear beh done
- 6, wait bch syndrome done, if done(first time for 3rd data packet syndrome done), reconfigure next DMA address ect. Then kick start next decode again.
- 7, repeat step 5 and step 6, if decode data packets no finish.
- 8, repeat step 5 two more times if all data had DMA input to BCH (wait last 2 data packet decode done)
- 9, decode finish

note:

During series decode several data packets , can not change BCTL0, BCTL1, BPSZ AND BF0CNT SFR configure.

```
Check error flag and correct data:
   Before correct data, check BHERR bit first,
      If 0, no error occur, return
      If 1, BCH detect error
    Then check BFAIL bit.
      If 1, Too many errors occur, BCH can not correct those errors, return
      If 0, BCH can correct those errors
Correct data:
   1, using CPU to correct data
     1,read error position start address from BCH controller
     2,read error position from SRAM
     3, read error data from SRAM
       4, correct data
    Eg:
    data reg[error position]=data reg[error position]^error data;
    // check error flag
    CHECKERR:
       JNB BCTL0.5, NO ERR DONE
             BCTL0.6, TOO M ERR
       CALL BCH XOR_ERR
       TOO M ERR:
       NO ERR DONE:
                         // no error or too many error
     RET
    // correct error data
    BCH XOR ERR:
    // get error bit count
       MOV R7, BECNT
    // get error position start address in SRAM
       MOV DPH, #0XA0
       MOV DPL, BXADR2
    BCH XOR BIT:
    // DPTR auto inc
       SETB DPAID
    // get error data byte address
       MOVX A, @DPTR
       MOV DP1L, A
       MOVX A, @DPTR
       MOV DP1H, A
    // get error data
```

```
MOVX A, @DPTR
MOV R8, A
INC DPTR // NOP INC

// change DPTR0 to DPTR1, disable DPTR auto inc
SETB DPSEL
CLR DPAID

// get & correct data
MOVX A, @DPTR
XRL A, R8
MOVX @DPTR, A
CLR DPSEL
BCH_NEXT_ERR:
DJNZ R7, BCH_XOR_BIT
RET
```

- 2 , using hardware to correct data
 - 1 , set mem_ctl to BCH correct data mode
 - 2, kick start correct data
 - 3, check correction done

13 SD Controller

13.1 SDC Register



1.SPND:SD pending flag register (Addr: 0xE8)

Position	7	6	5	4	3	2	1	0
Name	SPI_Mode	HW_RST_P ND	Align	Dato_sts	Dat_Tx _Pend	Dat_Rx _Pend	Rps_Tx _Pend	Cmd_Rx _Pend
Default	х	0	0	0	0	0	0	0
Access	RO	RO	R/W	RO	R/W	R/W	R/W	R/W

SPI_Mode: SPI Mode

0: not spi mode, maybe SD mode or MMC mode

1: spi mode

HW_RST_PND: HW reset pending

0: not pending

1: HW reset pending

Align: If DMA write data bytes can't divide by 4, you can set this bit to align the data before writing into flash.

0 = you need align the data by software

1 = can align the data auto

Dato_sts: Stop data TX

0 = Not Stop

1 = Stop Data TX Operation

Dat_Tx_Pend: Data TX Pending

0 = Not Pending

1 = Data TX Pending

Dat_Rx_Pend: Data RX Pending

0 = Not Pending

1 = Data RX Pending

Rps_Tx_Pend: Response TX Pending Or Response Fail

0 = Not Pending

1 = Rsponse TX Pending

Cmd_Rx_Pend: Command RX Pending

0 = Not Pending

1 = Command RX Pending

2.SCCTL: SD Command Control Register (Addr:0xE3)

Position	7	6	5	4	3	2	1	0
Name	Cmd_CRC_	SPI_CRC_C	Out_Rise	Cmd_CRC_e	Cmd8_rcv	DUAL_VOL	Manual	Get_Nxt

	Chk_Bit	hk		rr			_Rps	_Cmd
Default	0	0	0	0	0	1	0	0
Access	R/W	RO	R/W	RO	RO	-R/W	R/W	W0

Cmd_CRC_Chk_Bit: Command CRC Check enable

0 = Command CRC Check enable

1 = Command CRC Check disable

SPI_CRC_Chk: SPI CRC option ON/OFF(SPI CMD59)

0 = OFF

1 = ON

Out_Rise: Data out at Posedge or Negedge

0 = Posedge

1 = Negedge

Cmd_CRC_err: Command CRC Error

0 = Cmd RX Correctly

1 = Cmd RX Uncorrectly

Cmd8_rcv: Cmd8 auto response or manual response

0 = Cmd8 response by software

1 = Cmd8 auto response by hardware

DUAL_VOL: whether emmc device support dual voltage

0: EMMC not support dual voltage

1: EMMC support dual voltage

Manual_Rps: Manual Response Mode enable

0 = Auto Response By Hardware

1 = Response By Software

Get Nxt Cmd: Get Next Command

0 = Not Get Next Command

1 = Get Next Command



3.SRCTL: SD Response Control Register (Addr: 0xE7)

Position	7	6	5	4	3	2	1	0
Name	Rps_St_Byte _Clk	Rps_Cmd _ldx_Clk	Rps_End_Byte	e_Clk	Rps_Busy_E nSPI	Rps_CRC_C hk_Bit	No_Arg _Clk	Sdrps_ Start
Default	0	0	0	0	0	0	0	0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	WO

Rps_St_Byte_clk: Response Start Byte

0 = Response Start Byte is Cmd_index

1 = No Response start byte

Rps_Cmd_ldx_Clk:

If Rps_St_Byte_clk is 0:

0 = Response Start Byte is Cmd_index

1 = Response Start Byte is 0011_1111

If Rps_St_Byte_clk is 1:

No Response start byte

Rps_End_Byte_Clk:

Value	0_0	0_1	1_0	1_1
End_by te	CRC7	CRC7 for CID/CSD	FF	No end byte

Rps_Busy_EnSPI: Busy signal is transmitted after transmission of response (for SPI mode)

0 = Disable

1 = Enable

Rps_CRC_Chk_Bit: Rps CRC check enable

0 = Enable

1 = Disable

No_Arg_Clk: No argument

0 = Has argument

1 = No argument

Sdrps_Start: Rps TX start

0 = Not start

1 = Start

4.SDICTL: SD data RX config register (Addr: 0xDC)

Position	7	6	5	4	3	2	1	0
Name	Fbdat	Dat_CRC_er	Busy_Src		Busy_Cmd_e n	Cmd12_en	Clr_Busy	Rdat_en
Default	0	0	0	0	0	0	0	0
Access	R/W	RO	RO	RO	R/W	R/W	WO	R/W

Fbdat: Dataout bit sel

0 = One bit data out

1 = Four bits data out

Dat_CRC_err: Data TX CRC error

0 = Correct

1 = Data CRC error

Busy_Src:

00 = Valid reception

01 = Invalid reception



1x = Busy Cmd reception

Busy_Cmd_en: Busy Cmd Enable

0 = Disable

1 = Enable



Cmd12 en: Cmd12 stop data transmition enable 0 = Disable1 = Enable Clr_Busy: Clear busy data state 0 = Unclear 1 = Clear Rdat_en: Rx data enable 0 = Disable

1 = Enable

sddi_cfg = {fbdat, dat_crc_err, busy_src, busy_cmd_en, cmd12_en, 1'h0, rdat_en};

5.SDOCTL: SD data TX config register (Addr:0xE5)

Position	7	6	5	4	3	2	1	0
Name	Spi_out_bus	Spi_Cmd _Dis	Rca_Mat	Key_Rx _Enb	Sdc_Start	Dat_Sts _Val	Dat_Sts_Wer	Wdat_ start
Default	0	0	x	0	0	0	0	0
Access	R/W	R/W	RO	R/W	R/W	R/W	R/W	W0

Spi out busy:At SPI mode, card is at busy state, once clear busy, card jumps out of busy state immediately. Note: This bit is used for the card that can't clear busy after host stop clk.

0 = Once clear busy, after several clk, card jumps out of busy state.

1 = Once clear busy, card jumps out of busy state immediately.

Spi_Cmd_Dis: Disable Cmd RX(Only Used in SPI MODE)

0 = Enable Cmd RX

1 = Disable



Rca Mat: Cmd argument[31:16] match

0 = Dismatch

1 = Match

Key_RX_Enb: Argument Rx enable

0 = Diable

1 = Enable

0 = Not start

Sdc_Start: SD Cmd start



1 = Start

Dat_Sts_Val: Data: Data response token control about 'staus'

For SPI mode, if spi dat crc werr = 0:

If host care data crc result ,you should set this bit as "0"

if Status of data response token is 101, it means data CRC error

if Status of data response token is 010, it means Data Rx without CRC error

if host don't care data crc result, you should set this bit as "1"

Status of data response token is fixed with 010, Data accepted regardless of data crc error

Dat_Sts_Werr: Data response token control about 'staus'

For SPI mode, if spi_dat_crc_werr = 1, status of data response token is 110,Data rejected due to a write error

Wdat_start: Data TX start

0 = Not start

1 = Start

sddo_cfg = {1'b0, spi_cmd_dis, rca_mat, key_rx_enb, sdc_start, dat_sts_val, dat_sts_werr, 1'h0};

6.SFLAG: (Addr:0x90)

Position	7	6	5	4	3	2	1	0
Name	Busy_src		Card_sta_ inv	Cmd_sts_ dec[0]	Dat_crc_err	Rps_sts	Rca_mat	Cmd_crc_ err
Default	0	0	0	Х	0	0	Х	0
Access	RO	RO	RO	RO	RO	RO	RO	RO

Busy_Src:

00 = Valid reception

01 = Invalid reception

1x = Busy Cmd reception

Card_sta_inv: Card state invalid

0 = Card state valid

1 = Card state invalid

Cmd_sts_dec[0]: CMD END

0 = Cmd state is 1,2,or 3

1 = Cmd state is 0 ,it means cmd end

Dat_crc_err: Data TX CRC error

0 = CRC correct

1 = Error

Rps_sts: Card states valid or Cmd CRC correct

0 = Valid and correct

1 = No Response or Invalid or wrong

Rca_Mat: Cmd RCA match

0 = Dismatch

1 = Match

Cmd_crc_err: Cmd CRC error

0 = CRC correct

1 = error

7. SHCTL: SD Host Control (Addr:0xCD)

Position	7	6	5	4	3	2	1	0
Name	Cmd_Sts_Dec	•			bus_width8	Force_ Sdmod	CMD7_busy _en	Di_dat0 _clk
Default	X	x	x	x	0	0	1	х
Access	RO	RO	RO	RO	R/W	R/W	R/W	RO

Cmd_Sts_Dec: Cmd states decode

0001 = Cmd state is 00

0010 = Cmd state is 01

0100 = Cmd state is 10

1000 = Cmd state is 11

Bus width8:MMC bus width

0: 1bit or 4 bits bus

1: 8bits bus

Force_Sdmod: Force the card to change to SD Mode

0 = Keep current Mode

1 = Force to SD Mode

CMD7_busy_en: CMD7 busy enable //CMD7 need to send busy signal when RCA match.

0: needn't to send busy

1: need to send busy(default)

Di_dat0_chk: RX Data0

sdhost_cfg = {cmd_sts_dec, Bus_width8, force_sdmod, cmd7_rca_nchk, di_dat0_clk};

8:SR1CTL: (Addr:0xCE)

Position	7	6	5	4	3	2	1	0
Name	Reserved			App_cmd	Stop_dat_ auto	Reserved	R6_e	R1_e
Default	0	0	0	0	0	0	1	1
Access	-	-	-	R/W	R/W	-	R/W	R/W

App_cmd: Application CMD

0 = Not Application CMD

1 = Application CMD

Stop_dat_auto: Stop data transimit auto

R6_e: Response6 enable

0 = unable



1 = enable

R1_e: Response1 enable

0 = unable



1 = enable

9.SSTA: Card State Config (Addr:0xCF)

Position	7	6	5	4	3	2	1	0
Name	Reserved			Card_sta_upd ate	Card_sts			
Default	0 0			0	0			

Access	-	-	-	WO	R/W	R/W	R/W	R/W

Card_sta_update: Update Card status

0 : Card will go to "Card_sts" state regardless of current state.

1 : CMD_CRC_err = 0,Card will go to next Card state.

CMD_CRC_err = 1,Card will keep current Card state.

Card_sts: Card status

0000 = Idle

0001 = Ready

0010 = Ident

0011 = Standby

0100 = Tran

0101 = Data

0110 = Receive data

0111 = Program

1000 = Disconnect

1001 = bus_test

1010 = sleep

1011 = irq

1100 = Inactive

Others: Error

10.SDODLY: Rpsdo_cfg (Addr:0xD1)

Position	7	6	5	4	3	2	1	0		
Name	Rpsdo_dly							Rpsdo_dly_e		
Default	0									
Access	R/W	R/W								

Rpsdo_dly: Before Data start bit TX Rpsdo_dly * 8 delay cycle

Rpsdo_dly_e: Delay enable

0 = unable

1 = enable

11:SRCA0: (Addr:0xD2)

I	Position	7	6	5	4	3	2	1	0

Name	Rcal
Default	xxxx_xxxx
Access	RW

Rcal: RCA low byte

12.SRCA1: (Addr:0xD3)

Position	7	6	5	4	3	2	1	0	
Name	Rcah								
Default	xxxx_xxxx	XXXX_XXXX							
Access	R/W								

Rcah: RCA high byte

13.SDOTK: Data TX start token(For SPI data out only) (Addr:0xDD)

Position	7	6	5	4	3	2	1	0
Name	Do_token							
Default	xxxx_xxxx							
Access	R/W							

Do_token: Data TX start token

For single block read:
Only first byte: Start Block

1	1	1	1	1	1	1	0

14.SDXADR0: (Addr:0xD4)

Position	7	6	5	4	3	2	1	0		
Name	Mem_adr_dat	Mem_adr_dat_sdc[7:0]								
Default	xxxx_xxxx	xxxx_xxxx								
Access	wo									

Mem_adr_dat_sdc[7:0]: DMA addr 7 to 0 for data

15:SDXADR1: (Addr:0xD5)

Position	7	6	5	4	3	2	1	0	
Name	Reserved				Mem_adr_dat_sdc[12:8]				
Default	XXXX				xxxx				
Access	-				wo				

Mem_adr_dat_sdc[12:8]: DMA addr 12 to 8 for data

16.SRXADR0: (Addr:0xD6)

Position	7	6	5	4	3	2	1	0
Name	Mem_adr_cm	d_sdc[7:0]						
Default	xxxx_xxxx							
Access	wo							

Mem_adr_cmd_sdc[7:0]: DMA addr 7 to 0 for Cmd

17:SRXADR1: (Addr:0xD7)

Position	7	6	5	4	3	2	1	0	
Name	Reserved				Mem_adr_cmo	d_sdc[12:8]			
Default	xxxx				XXXX				
Access	-				WO				

Mem_adr_cmd_sdc[12:8]: DMA addr 12 to 8 for Cmd

18.SRDL0: (Addr:0xDE)

Position	7	6	5	4	3	2	1	0
Name	Dma_no_byte	I_cmd						
Default	0000_0000							
Access	WO							

Dma_no_bytel_cmd: Dma_no_bytel_cmdbytes for Cmd reception and Rps transmission

19:SRDL1: (Addr:0xDF)

Position	7	6	5	4	3	2	1	0
Name	Apu	Force_ cmd12	Tokchk		Dat_not _mat	Reserved		Dma_no_ byteh_cmd
Default	0	0	0		0	х		0
Access	wo	wo	WO		WO	Х		WO

Apu: Cmd output enable

0 = Cmd output disable

1 = Cmd output enable

Force_cmd12: Force the card to transmition

0 = Keep transmition

1 = Stop transmition

Tokchk: Token check

0x = Check Multiple block write start token for SPI Mode

x0 = Check single block read ,write and Multiple block read start token for SPI Mode

11 = Stop tran token

Dat_not_mat: Data out not match

0 = match

1 = Not match

Dma_no_byteh_cmd: Cmd reception and Rps transmission bytes
={ Dma_no_byteh_cmd , Dma_no_bytel_cmd} +1

20.SDDL0:	(Addr:0xE1)	2

Position	7	6	5	4	3	2	1	0
Name	Dma_no_byte	l_dat						
Default	xxxx_xxxx							
Access	WO							

21:SDDL1: (Addr:0xE2)

Position	7	6	5	4	3	2	1	0
Name	Reserved							Dma_no_bytel_cmd
Default	xxxx_xxxx							
Access	-							WO

Dma_no_byteh_dat: has {{dma_no_byteh_dat,dma_no_bytel_dat}+1}bytes data for rx or tx Data in memory after RX:

For example dma_no_byte = n



When n%4 =

1: the last 1 byte data in memory : {data_n,24'h0}

2: the last 2 bytes data in memory :{data_n,data_(n-1),16'h0}

3: the last 3 bytes data in memory :{data_n,data_(n-1),data_(n-2),8'h0}

0: the last 4 bytes data in memory :{data_n,data_(n-1),data_(n-2),data_(n-3)}

22:SRDCTL: (Addr:0xE4)

Position	7	6	5	4	3	2	1	0
Name	Rps_dly_en	Rps_dly_NO						
Default	xxxx_xxxx							
Access	WO							

Rps_dly_no: Rps delay "Rps_dly_no + 4" SD clock after Cmd received

Rps_dly_en: Rps delay enable

0 = disable1 = enable

23.SINDX: (Addr:0xE6)

Position	7	6	5	4	3	2	1	0
Name	Reserved		CMD_index					

Default	0		XX_XX	XX					
Access	-		RO						
CMD_ind	lex: Commar	nd index							
00_0000	11_1111	1: Cmd0 to	Cmd63,soı	me Cmds are	reserved				
24:SARG	0: (Add	r:0xE9)							
Position	7	6	5	4	3	2	1	0	
Name	CMD_ARG	CMD_ARG0(RD)/KEYL(WR)							
Default	xxxx_xx	xxxx_xxxx							
Access	R/W								
CMD_AR	G0/KEYL:	D/KEYL:CMD argument when read and Keyl when write							
25.SARG	61: (Add	r:0xEA)							
Position	7	6	5	4	3	2	1	0	
Name	CMD_ARG	31(RD)/KEYH(WR)	<u> </u>	'	'	1		
Default	YYYY YY	CMD_ARG1(RD)/KEYH(WR)							
Delault	_\\\\	xxxx_xxxx							
Access	R/W		ment when	read and Ke	yh when wri	te			
Access CMD_AR	R/W		ment when	read and Ke	yh when wri	te			
Access	R/W	CMD argur	ment when	read and Ke	yh when wri	te 2	1	0	
Access CMD_AR 26:SARG	R/W RG1/KEYH :	CMD argur ::0xEB)					1	0	
Access CMD_AR 26:SARG Position	R/W RG1/KEYH : G2: (Addr	CMD argur ::0xEB) 6					1	0	
Access CMD_AR 26:SARG Position Name	R/W RG1/KEYH: G2: (Addr 7 CMD_ARG	CMD argur ::0xEB) 6					1	0	
Access CMD_AR 26:SARG Position Name Default Access	R/W RG1/KEYH: G2: (Addr CMD_ARG XXXX_XX	CMD argur					1	0	
Access CMD_AR 26:SARG Position Name Default Access	R/W RG1/KEYH: G2: (Addr 7 CMD_ARG XXXX_XXX	CMD argur					1	0	
Access CMD_AR 26:SARG Position Name Default Access CMD_AR	R/W RG1/KEYH: G2: (Addr 7 CMD_ARG XXXX_XXX RO RG2: CMD a	CMD argur					1	0	
Access CMD_AR 26:SARG Position Name Default Access CMD_AR	R/W RG1/KEYH: G2: (Addr 7 CMD_ARG XXXX_XXX RO RG2: CMD a	CMD argur					1	0	
Access CMD_AR 26:SARG Position Name Default Access CMD_AR 27:SARG	R/W RG1/KEYH: G2: (Addr 7 CMD_ARG XXXX_XXX RO RG2: CMD a	CMD argur :0xEB) 6 6 cz cx argument dr:0xEC) 6	5	4	3	2			
Access CMD_AR 26:SARG Position Name Default Access CMD_AR 27:SARG Position Name	R/W RG1/KEYH: G2: (Addr 7 CMD_ARG XXXX_XXX RO RG2: CMD a	CMD argur :0xEB) 6 6 c2 cxx argument dr:0xEC) 6 6	5	4	3	2			
Access CMD_AR 26:SARG Position Name Default Access CMD_AR 27:SARG Position	R/W RG1/KEYH: G2: (Addr 7 CMD_ARG XXXX_XXX RO RG2: CMD a G3: (Addr 7 CMD_ARG	CMD argur :0xEB) 6 6 c2 cxx argument dr:0xEC) 6 6	5	4	3	2			
Access CMD_AR 26:SARG Position Name Default Access CMD_AR 27:SARG Position Name Default Access	R/W RG1/KEYH: G2: (Addr 7 CMD_ARG XXXX_XXX RO G3: (Addr 7 CMD_ARG XXXX_XXX RO RO RO RO RO RO	CMD argur CMD argur	5	4	3	2			
Access CMD_AR 26:SARG Position Name Default Access CMD_AR 27:SARG Position Name Default Access CMD_AR	R/W RG1/KEYH: G2: (Addr 7 CMD_ARG XXXX_XXX RO G3: (Addr 7 CMD_ARG XXXX_XXX RO RO RG2: CMD a	CMD argur CMD argur	5	4	3	2			
Access CMD_AR 26:SARG Position Name Default Access CMD_AR 27:SARG Position Name Default Access	R/W RG1/KEYH: G2: (Addr 7 CMD_ARG XXXX_XXX RO G3: (Addr 7 CMD_ARG XXXX_XXX RO RO RG2: CMD a	CMD argur CMD argur CMD argur 6 6 6 6 6 6 6 6 6 6 6 6 6	5	4	3	2			

Default

1

7'h0

Access RO W/R

DONE:When write to SD_CLK_COUNTER, DONE will turn "0",hardware starts to count SD_CLK untill equal to SD_CLK_COUNTER,then DONE will turn "1".

SD_CLK_COUNTER:SD_CLK_COUNTER*2=SD host CLK cycles you want to count.Mean that if you want to

count "M" SD host clk cycles, you should set SD_CLK_COUNTER equal half of "M". eg: if you want to count 40 SD host clk cycles, you need only set SD_CLK_COUNTER equal 20. When SD_CLK_COUNTER = 7f,the maximum SD host clk cycles you can count up to FE(254 SD host clk cycles).

IF you change the SD_CLK_COUNTER when hardware is counting, it will start to count from "0"untill equal to

the latest SD_CLK_COUNTER.

29:Last_CMD: (Addr:0xBA)

Position	7	6	5	4	3	2	1	0
Name		HCS	Last_cmd					
Default		х	х	х	х	x	x	х
Access	0	RO	RO	RO	RO	RO	RO	RO

HCS: High capacity device

0 = less than or equal 2GB

1 = more than 2GB

Last_cmd:Host last sent CMD and device responsed correctly.

30:BOOT CFG: (Addr:0xBD)

Position	7	6	5	4	3	2	1	0
Name	MMC_SD	Boot_dat_star t	Boot_dat_en d	BOOT_EN	Cmd_low_m7 4	Cmd0_rst	Cmd0_f0	Cmd0_fa
Default	0	0	0	1	0	0	0	0
Access	RO	RO	RO	R/W	RO	RO	RO	RO

MMC SD: Hard ware detect SD and MMC

0 = MMC device

1 = SD device

Boot_dat_start: device begin to send boot data

0 = device can't start to send boot data.

1 = device can start to send boot data

Boot_dat_end: device stop sending boot data.

0 = go on sending

1 = stop sending

BOOT_EN:boot enable

0 = boot unable

1 = boot enable

Cmd_low_m74: CMD line low more than 74 CLK

0 = less than 74 CLK

1 = more than 74 CLK

Cmd0_rst:CMD0 with arg = 32'h0

Cmd0_f0:CMD0 with arg = 32'hf0f0_f0f0

Cmd0_fa:CMD0 with arg = 32'hffff_fffa

13.2 SD Mode Operation

1. SD MODE R1 Response Operation:

// Config DMA Address

MOV SRXADR0, #21H

MOV SRXADR1, #01H

// Config DMA Length 4 Bytes

MOV SRDL0, #3H

MOV SRDL1, #0H

// Config R1 Response Enable

MOV SR1CTL, #01H

// Kick Start Response Transmission

MOV SRCTL, #01H

2. SD MODE R2 Response Operation:

// Config DMA Address

MOV SRXADR0, #21H

MOV SRXADR1, #01H

// Config DMA Length 15 Bytes

MOV SRDL0, #14

MOV SRDL1, #0H

// Kick Start Response Transmission, CRC7 for CID/CSD

MOV SRCTL, #51H

3. SD MODE R3 Response Operation:

// Config DMA Address

MOV SRXADR0, #21H

MOV SRXADR1, #01H

// Config DMA Length 4 Bytes

MOV SRDL0, #3

MOV SRDL1, #0H

// Kick Start Response Transmission

MOV SRCTL, #61H

4. SD MODE R6 Response Operation:

// Config DMA Address

MOV SRXADR0, #21H

MOV SRXADR1, #01H

// Config DMA Length 4 Bytes

MOV SRDL0, #3

MOV SRDL1, #0H

// Config R6 Response Enable

MOV SR1CTL, #02H

// Kick Start Response Transmission

MOV SRCTL, #01H

5. SD MODE R7 Response Operation:

// Config DMA Address

MOV SRXADR0, #21H

MOV SRXADR1, #01H

// Config DMA Length 4 Bytes

MOV SRDL0, #3

MOV SRDL1, #0H

// Kick Start Response Transmission

MOV SRCTL, #01H

6. SD MODE Data Output Operation:

// Config DMA Address

MOV SDXADR0,#21H

MOV SDXADR1,#01H

// Config DMA Length 64 Bytes

MOV SDDL0,#63

MOV SDDL1,#00

// Kick Start Data Transmission

ORL SDOCTL,#(1 << 0)

7. SD MODE Data Recieve Operation:

// Config DMA Address

MOV SDXADR0,#21H

MOV SDXADR1,#01H

// Config DMA Length 64 Bytes

MOV SDDL0,#63

MOV SDDL1,#00

// Kick Start Data Recieve

13.3 SPI Mode Operation

1. SPI MODE R1 Response Operation:

// Config DMA Address

MOV SRXADR0,#21H

MOV SRXADR1,#01H

// Config DMA Length 1 Bytes

MOV SRDL0,#0

MOV SRDL1,#0

// Kick Start Response Transmission

MOV SRCTL,#11110001B

2. SPI MODE R2 Response Operation:

// Config DMA Address

MOV SRXADR0,#21H

MOV SRXADR1,#01H

// Config DMA Length 2 Bytes

MOV SRDL0,#1

MOV SRDL1,#0

// Kick Start Response Transmission

MOV SRCTL,#11110001B

3. SPI MODE R3 Response Operation:

// Config DMA Address

MOV SRXADR0,#21H

MOV SRXADR1,#01H

// Config DMA Length 5 Bytes

MOV SRDL0.#4

MOV SRDL1,#0

// Kick Start Response Transmission

MOV SRCTL,#11110001B

4. SPI MODE R7 Response Operation:

// Config DMA Address

MOV SRXADR0,#21H

MOV SRXADR1,#01H

// Config DMA Length 5 Bytes

MOV SRDL0,#4

MOV SRDL1,#0

// Kick Start Response Transmission

MOV SRCTL,#11110001B

5. SPI MODE Data Transmission and receive operation is the same as SD mode

13.4 EXINST Opcode Summary

Table 13-1: EXINST Opcode

	Mnemonics		Opcode		Flags
		1st Byte	2nd Byte	3rd Byte	
MOV32	ERn, EDPi	1010 0101	1110 nn0i		EZ
	EDPi, ERn	1010 0101	1110 nn1i		
	ERn, ERm	1010 0101	0100 nnmm		
	ER4, ERn	1010 0101	1001 nn00		
	ERn, ER4	1010 0101	1001 nn10		
NOT32	ERn	1010 0101	0001 nn00		
INC32	ERn	1010 0101	0001 nn10		EZ
DEC32	ERn	1010 0101	0001 nn11		EZ
RAN32	EDPi, ERn	1010 0101	0000 nn1i		
ANL32	ERn, EDPi	1010 0101	0010 nn0i		EZ
	EDPi, ERn	1010 0101	0010 nn1i		
	ERn, ERm	1010 0101	0011nnmm		
ORL32	ERn, EDPi	1010 0101	0100 nn0i		EZ
	EDPi, ERn	1010 0101	0100nn1i		
	ERn, ERm	1010 0101	0101 nnmm		
XRL32	ERn, EDPi	1010 0101	0110nn0i		EZ
	EDPi, ERn	1010 0101	0110 nn1i		
	ERn, ERm	1010 0101	0111 nnmm		
ADD32	ERp, EDPi, ERn	1101 0100	00pp nn0i		EZ, EC
	EDPi, ERn, ERp	1101 0100	00pp nn1i		
	ERp, ERn, ERm	1101 0100	01pp nnmm		
SUB32	ERp, EDPi, ERn	1101 0100	10pp nn0i		EZ, EC
	EDPi, ERn, ERp	1101 0100	10pp nn1i		
	ERp, ERn, ERm	1101 0100	11pp nnmm		
ROTR32	ERn, ER8	1010 0101	1101 nn00		
ROTL32	ERn, ER8	1010 0101	1101 nn01		
ROTR8	EACC, ER8	1010 0101	1000 0000		
ROTL8	EACC, ER8	1010 0101	1000 0001		
CLR32	ERn	1010 0101	0001 nn01		
ADDDPi		1010 0101	0000 010i		
SUBDPi		1010 0101	0000 110i		

INCDPi		1010 0101	0000 000i	
DECDPi		1010 0101	0000 100i	
INC4DPi		1010 0101	1101 0i11	
DEC4DPi		1010 0101	1101 1i11	
MUL16	ERn	1010 0101	1100 nn00	EZ
DIV16	ERn	1010 0101	1101 nn10	

Notes:

ERn, ERm, ERp:

32-bit register *ER0-ER3*. n=m=p is allowed.

ERni, ERmj:

8-bit SFR *R00-R03*, *R10-R13*, *R20-R23*, *R30-R33*. ni=mj is allowed.

EDPi:

XRAM addressing pointer *DPTR0* or *DPTR1*.

ER8:

8-bit SFR R8.

EACC:

8-bit SFR ACC.

14 Random data generator

CMPCTI

CIVIL									
Position	7	6	5	4	3	2	1 0		
Name		MODESEL		CPLAST	CPLOAD	CPDISEL	LBCNT		
Default	0	0	0	0	0	0	0	0	
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	

MODESEL: Mode Select

000: IDLE mode.

001: Compare mode. Calculate the different bit amount.

011: NandFlash read SRAM XOR mode. While NandFlash module reads data from SRAM, the data will XOR with a random value.

100: DMA mode, RCMP module reads data from SRAM , and XOR a random value, then write the data to the

same address with read address. When DMA done, DMA mode will return to the IDLE mode.

101: NandFlash write SRAM XOR mode. While NandFlash module writes data to SRAM, the data will XOR with a random value.

110: Bad Column Search mode.可以将错误的byte地址写到SRAM中,16Bit flash和8x2flash 同样,均是以byte为单位来表示地址。

(注意: 使能这个功能且读flash速度最快时,不能有除nandflash外 DMA优先级比BCS高的模块在和BCS使用同一块memory,优先级比BCS高的模块有USB,nandflash,BCH,sd host;而且NFC也不能与优先级比它高的DMA同时使用同一块memory,优先级比NFC高的模块有USB)

CPLAST: Last compare enable (While CPDISEL is 0, this bit do not work).

0: Disable;

1: Enable;

CPLOAD: Load the random data every clock (While CPDISEL is 0, this bit do not work).

0: Disable;

1: Enable;

CPDISEL: Compare data source select.如果是bad column search mode时,这位必须为0.

0: Compare data from nand flash.

1: Compare data from ER0



LBCNT: Last compare byte amount select.如果这时有坏列管理(BCM),则这个寄存器应该填有效数据的最后一次DMA的byte的数量。例如从flash读出的数据有9byte,但是坏列有2个,则有效数据为7byte,这时LBCNT应该填3。

00: 4 byte

01: 1 byte

10: 2 byte 11: 3 byte



CMPCTL1

Position	7	6	5	4	3	2	1	0
Name			_		BCSDONE	LASTPT	TESTEN	FIXEN
Default					0	0	0	0
Access					R	R	R/W	R/W

BCSDONE: bad column search done flag. 退出 Bad Column Search mode后这个寄存器会清零。 0:not done

1:done

LASTPT:最后一次坏列地址DMA是否为完整的32bit

0:最后一次坏列地址DMA为完整的32bit;

1:最后一次坏列地址DMA为单个16bit。这时最后一个坏列地址会被copy 1次,凑够32bit写到sram中。

退出 Bad Column Search mode后这个寄存器会清零。

TESTEN: DMA test enable. Only used in DMA mode.

0: Disable, DMA mode work normally.

1. Enable, DMA mode will not read data from SRAM, and only write the random data to SRAM

FIXEN: Fix data enable. It can be used for all mode.

- 0: Disable fixes data, the data will be random
- 1. Enable fixes data, the data will not change

CMPSTADR

Position	7	6	5	4	3	2	1	0	
Name	STAI	DDRL	STADDRH/ STADDRL						
Default	0	0	0	0	0	0	0	0	
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	

DMA start address: It is used for DMA mode. Must write the high address first (13 \sim 8bits), and then write the (7 \sim 0bits). This address is equal to (XRAM address >> 2).

读这个寄存器时,第一次读高6bit(13~8bit),第二次读低8bit(7~0bits)。每完成1次DMA,这个寄存器会自动加1。(SRAM物理地址)

CMPDMAMT

Position	7	6	5	4	3	2	1	0		
Name	CN	MPDMAM'	TL	CMPDMAMTH/ CMPDMAMTL						
Default	0	0	0	0	0	0	0	0		
Access	W	W	W	W	W	W	W	W		

DMA 32bit data amount: It is used for DMA mode. Must write the high bit first (10~8bits), and then write the (7~0bits). This SFR is equal to the 32bit data amount -1. If you want to DMA one data, you can write 0 to this SFR.

CPERCNT

Position	7	6	5	4	3	2	1	0					
Name		Compare counter											
Default	0	0	0	0	0	0	0	0					
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W					

CPERCNT: This count will calculate the different bits amount that is between FIFO data and ERO or FIFO data and NandFlash data. 在bad column search mode时,这个寄存器的功能跟compare mode一样。

CMPFIFO

Position	7	6	5	4	3	2	1	0				
Name		Compare FIFO										
Default	0	0	0	0	0	0	0	0				
Access	W	W	W	W	W	W	W	W				

Write this SFR to configure the seed, must write 4 times. Firstly write the $7\sim0$ bits, and then write the $15\sim8$ bits, and then write the $23\sim16$ bits, finally write the $31\sim24$ bits;

Operation Guide

Compare mode

```
    Write the 32bits seed to the CMPFIFO: (The seed is 0x12345678 in this example)
    CMPFIFO = 0x78;
    CMPFIFO = 0x56;
```

CMPFIFO = 0x34; CMPFIFO = 0x12;

- 2. If need another function, you can change CMPCTL or CMPCTL1.(This example is not change)
- 3. Enable the compare mode , and select the last compare byte amount : CMPCTL = 0x20 :
- 4. If finish compare , read the CMPCNT, and then select IDLE mode to clear CMPCNT.

NandFlash read SRAM XOR mode

1. Write the 32bits seed to the CMPFIFO : (The seed is 0x12345678 in this example)

```
CMPFIFO = 0x78;

CMPFIFO = 0x56;

CMPFIFO = 0x34;

CMPFIFO = 0x12;
```

2. Write the XOR data amount: (This example is 0x0100(32bit data amount).) unsigned int temp;

```
temp = 0x0100 - 0x01;

CMPDMAMT = (temp >> 8);

CMPDMAMT = temp & 0x00FF;
```

3. Enable the NandFlash read SRAM XOR mode :

CMPCTL = 0x60;

4. Then the NandFlash module read data from SRAM will XOR a random value.

NandFlash Write SRAM XOR mode

1. Write the 32bits seed to the CMPFIFO : (The seed is 0x12345678 in this example)

```
CMPFIFO = 0x78;

CMPFIFO = 0x56;

CMPFIFO = 0x34;

CMPFIFO = 0x12;
```

2. Write the XOR data amount: (This example is 0x0100(32bit data amount).) unsigned int temp;

```
temp = 0x0100 - 0x01;
CMPDMAMT = (temp >> 8);
CMPDMAMT = temp & 0x00FF;
```

3. Enable the NandFlash write SRAM XOR mode :

CMPCTL = 0xA0;

4. Then the NandFlash module write data to SRAM will XOR a random value.

DMA mode

```
1. Write the 32bits seed to the CMPFIFO: (The seed is 0x12345678 in this
  example)
  CMPFIFO = 0x78;
  CMPFIFO = 0x56;
  CMPFIFO = 0x34;
  CMPFIFO = 0x12:
2. Write the DMA start address: (This example is 0x1000(XRAM \text{ address}))
   unsigned int temp;
  temp = 0x1000 >> 2;
  CMPSTADR = (temp >> 8);
  CMPSTADR = temp & 0x00FF;
3. Write the DMA amount: (This example is 0x0100(32bit data amount).)
   unsigned int temp;
  temp = 0x0100 - 0x01;
  CMPDMAMT = (temp >> 8);
  CMPDMAMT = temp & 0x00FF;
4. Enable the DMA mode:
  CMPCTL = 0x80;
5. Wait the MODESEL clear;
DMA test mode
   Write the 32bits seed to the CMPFIFO: (The seed is 0x12345678 in this
example)
  CMPFIFO = 0x78;
  CMPFIFO = 0x56;
  CMPFIFO = 0x34:
  CMPFIFO = 0x12;
2. Write the DMA start address: (This example is 0x1000(XRAM address))
   unsigned int temp;
  temp = 0x1000 >> 2;
  CMPSTADR = (temp >> 8);
  CMPSTADR = temp & 0x00FF;
    Write the DMA amount: (This example is 0x0100(32bit data amount).)
   unsigned int temp;
  temp = 0x0100 - 0x0001;
  CMPDMAMT = (temp >> 8);
  CMPDMAMT = temp & 0x00FF;
   Enable the DMA test mode:
  CMPCTL1 = 0x02;
5. Enable the DMA mode:
  CMPCTL = 0x80;
Wait the MODESEL clear;
```

Bad column search mode

(注意:使能这个功能且读flash速度最快时,不能有除nandflash外 DMA优先级比BCS高的模块在和BCS使用同一块memory,优先级比BCS高的模块有USB,nandflash,BCH,sd host;而且NFC也不能与优先级比它高的DMA同时使用同一块memory,优先级比NF高的模块有USB)

1. Write the 32bits seed to the CMPFIFO: (The seed is 0x12345678 in this

example)

CMPFIFO = 0x78;

CMPFIFO = 0x56;

CMPFIFO = 0x34;

CMPFIFO = 0x12;

2. Write the DMA start address: (This example is 0x1000(逻辑地址)),坏列地址 将会被写入到sram这里去

unsigned int temp;

temp = 0x1000 >> 2;//0X400

CMPSTADR = temp >> 8;

CMPSTADR = temp & 0x00FF;

3. Enable the compare mode , and select the last compare byte amount 1 byte; (注意, BCS mode只支持nandflash DMA到SRAM的情况,即CPDISEL必须为0)

CMPCTL = 0xC1;

- 4. Read nandflash and wait it done;
- 5. wait BCSDONE:

while(~(CMPCTL1 & 0X08));

6. 读该次操作总错误bit数(可选)

i= CPERCNT;

7. 读当前的SRAM address和LASTPT:

temp = CMPSTADR:

temp = (temp << 8) | CMPSTADR;

i= CMPCTL1 & 0X04;

假如得出temp = 0x402且LASTPT为0,则说明出现了4个错误的byte,这4个错误的byte按出现的先后顺序,其地址和错误bit数($1\sim8$)会分别存放在SRAM中,如下图:

0X402	EMPTY	EMPTY
0X401	ErrByte3(16BIT)	ErrByte2(16BIT)
0X400	ErrByte1(16BIT)	ErrByte0(16BIT)

假如得出temp = 0x402且LASTPT为1,则说明出现了3个错误的byte,这3个错误的byte按出现的先后顺序,其地址和错误bit数(1~8)会分别存放在SRAM中,如下图:

0X402	EMPTY	EMPTY
0X401	ErrByte2(16BIT)	ErrByte2(16BIT)
0X400	ErrByte1(16BIT)	ErrByte0(16BIT)

其中每个16bit的格式如下:

注意Address指的是这个Byte在这次操作中的DMA序列,NF_CTL每读够4个byte就会往SRAM DMA一次,例如第一次DMA的第3byte错了,则这个地址为2,如果第二次DMA的第一个byte错了,则地址为4,依此类推。16Bit flash和8x2flash同样,均是以byte为单位来表示地址。

Error bit amount表示这个byte有多少bit错了, 0表示1bit错, 7表示8bit错。

Byte0		Erro Bit mou							Ad	ddre	ss					
BIT	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0

8. Disable Bad Column Mode:

CMPCTL = 0X00

15 Electrical Characteristics

15.1 Absolute Maximum Ratings

Symbol	Parameter	MIN	MAX	Unit
VDD	DC Power Supply	-0.3	+3.6	V
Vin	Input Voltage	VSS-0.3	VDD+0.3	V
Vout	Output Voltage	VSS-0.3	VDD+0.3	V
Та	Operating Temperature	0	+75	°C
Tst	Storage Temperature	-40	+125	°C

15.2 Recommended Operating Conditions

Symbol	Parameter	MIN	TYP	MAX	Unit
VDD	Supply Voltage	3.0	3.3	3.6	V
VDD18	Supply Voltage	1.62	1.8	1.98	V
Vin	Input Voltage		-	VDD	V
Tamb	Ambient Temperature	0	-	+70	°C

15.3 Electrical Characteristics of 3.3V I/O Cell

Symbol	Parameter	CONDITIONS	Limits			
			MIN	TYP	MAX	Unit
VDD	Power Supply	3.3V I/O	3.0	3.3	3.6	V
Vil	Input Low Voltage	LVTTL			0.8	V
Vih	Input High Voltage		2			V
Vol	Output Low Voltage	lol =~8/16mA			0.4	V
Voh	Output High Voltage	IoI =~8/16mA	2.4			V
Rpu	Input Pull-up Resistance	Vin = 0		30K		ohm

15.4 Electrical Characteristics of RC

Symbol	Parameter	MIN	TYP	MAX	Unit
RC output	Low power output		10		MHz (trim value =
	High performance output		70		5'b10000)
Tamb	Ambient Temperature	0	-	+70	°C

15.5 Electrical Characteristics of LDO

Symbol	Parameter	MIN	TYP	MAX	Unit
VDDIO	Supply Voltage	2.0	3.3	3.6	V
VDD18	LDO output	1.62	1.8	1.98	V

BORB	BOR trigger Voltage 1.9		1.9		V
lvdd18	LDO output driving		150	mA	
Tamb	Ambient Temperature	0	-	+70	°C

Appendix Revision History

Date	Version	Revised items	Revised by
11年12月22日	0.0.1	1.	zhangjing jing_zhang@buildwin.com.cn
		1.	
		1.	
		1.	
		1.	

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